

The European XFEL Project



Ulrich Trunk
Deutsches Elektronen-Synchrotron DESY

Outline

- The XFEL Machine
 - Electron Accelerator
 - Undulator Sources
- Experiments
 - XPCS Photon Correlation Spectroscopy
 - XCDI Coherent Diffraction Imaging
- 2D Area Detectors
 - Large Pixel Detector (LPD)
 - DEPFET Active Pixel Sensor (DEPFET-APS)
 - Hybrid Pixel Array Detector (HPAD)

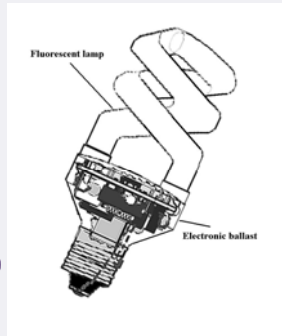
X-Ray Sources

Light bulb



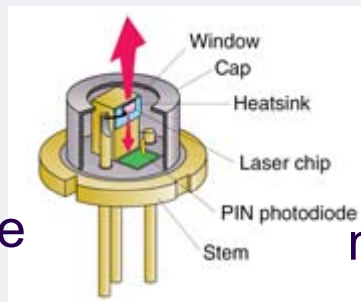
incoherent,
white spectrum

Fluorescent
lamp
(e.g. Hg, Ne)

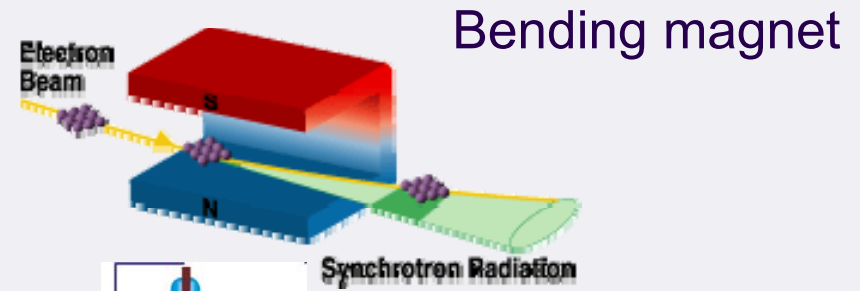


incoherent,
Line spectrum

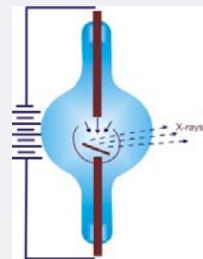
Laser diode



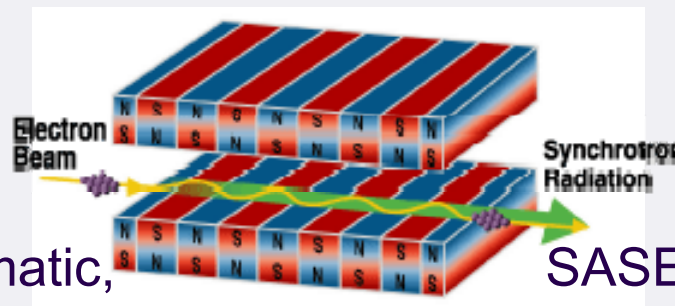
monochromatic,
coherent



Bending magnet

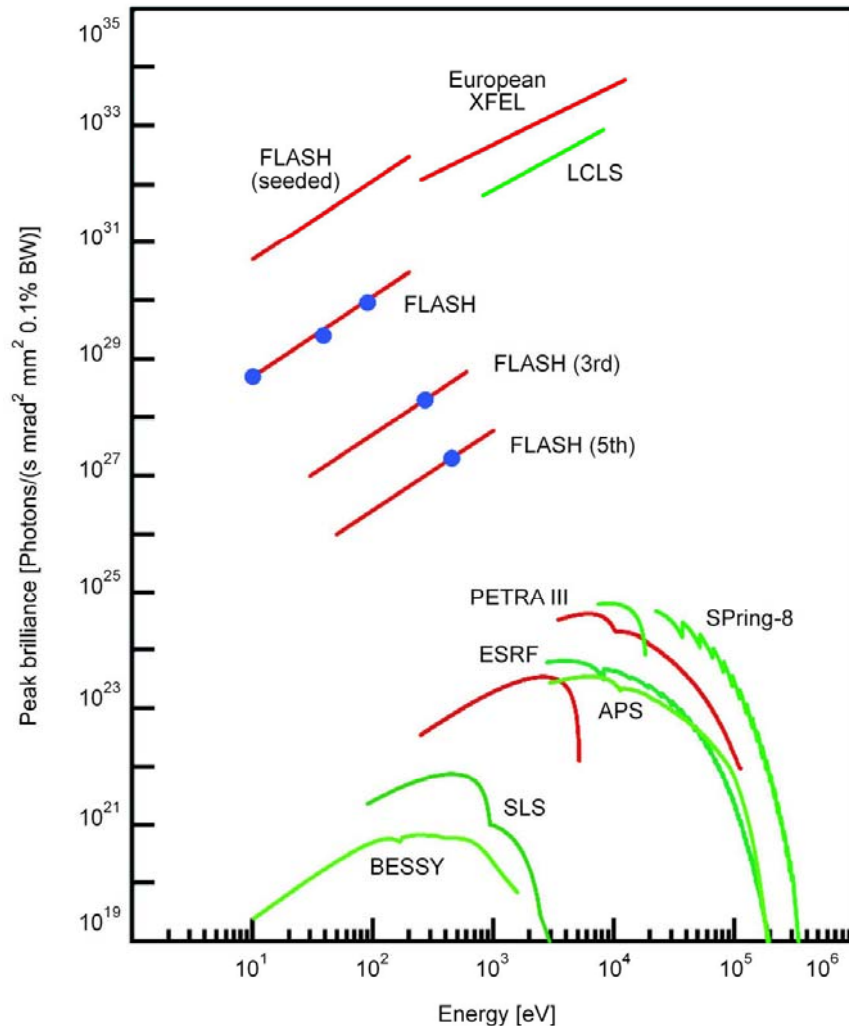


X-ray tube



SASE undulator

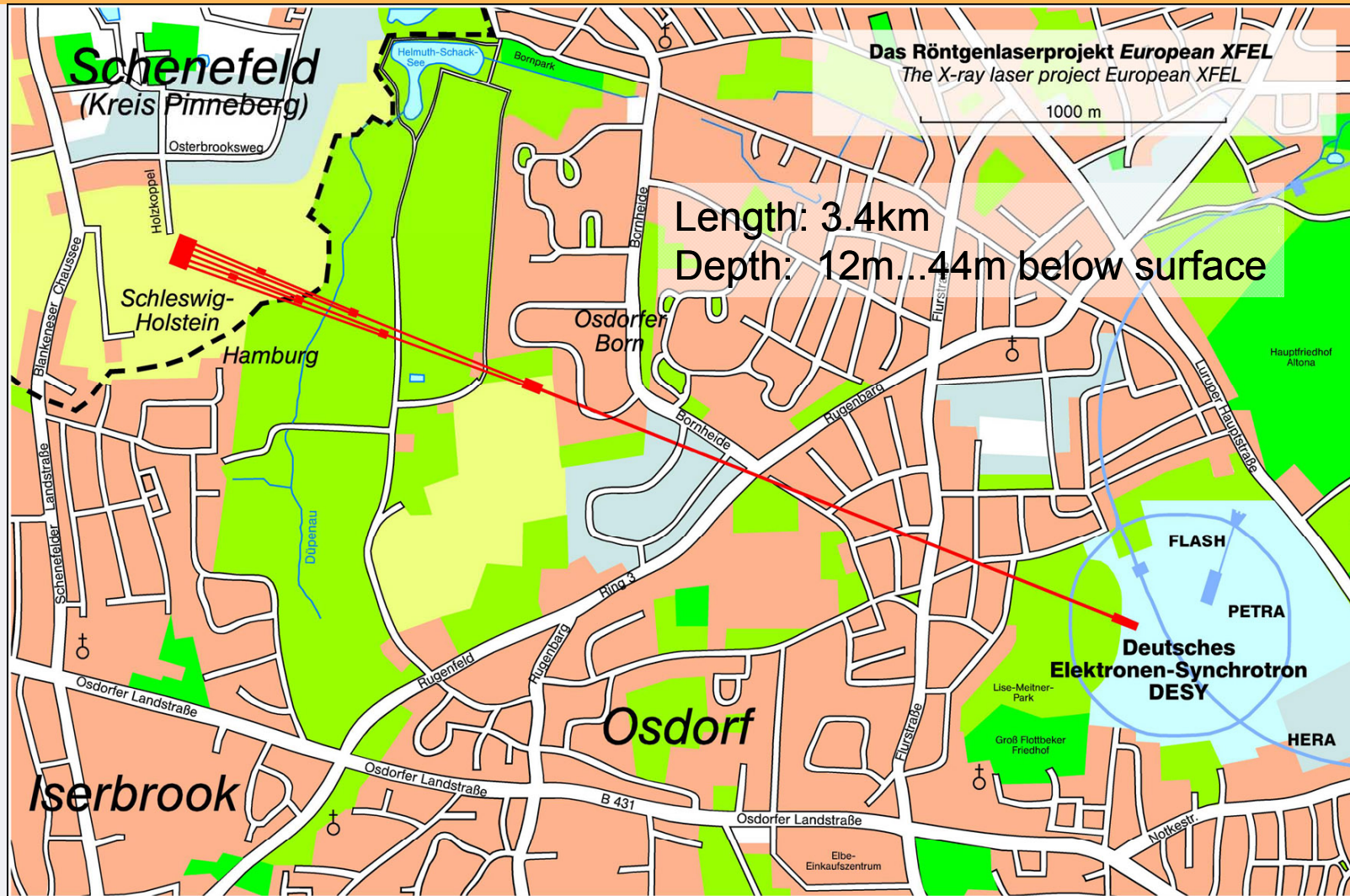
The European XFEL Key Parameters



- Superconducting linac driven
- SASE undulators
- 10^{33} ph/(s mm² mrad² 0.1%BW) peak brilliance
 - 10^9 wrt. 3rd gen. synchrotrons
 - 10^5 in av. brilliance
- $E_\gamma = 250\text{eV} \dots 12\text{keV}$
- 100fs pulse width
- 3000 pulses@5MHz

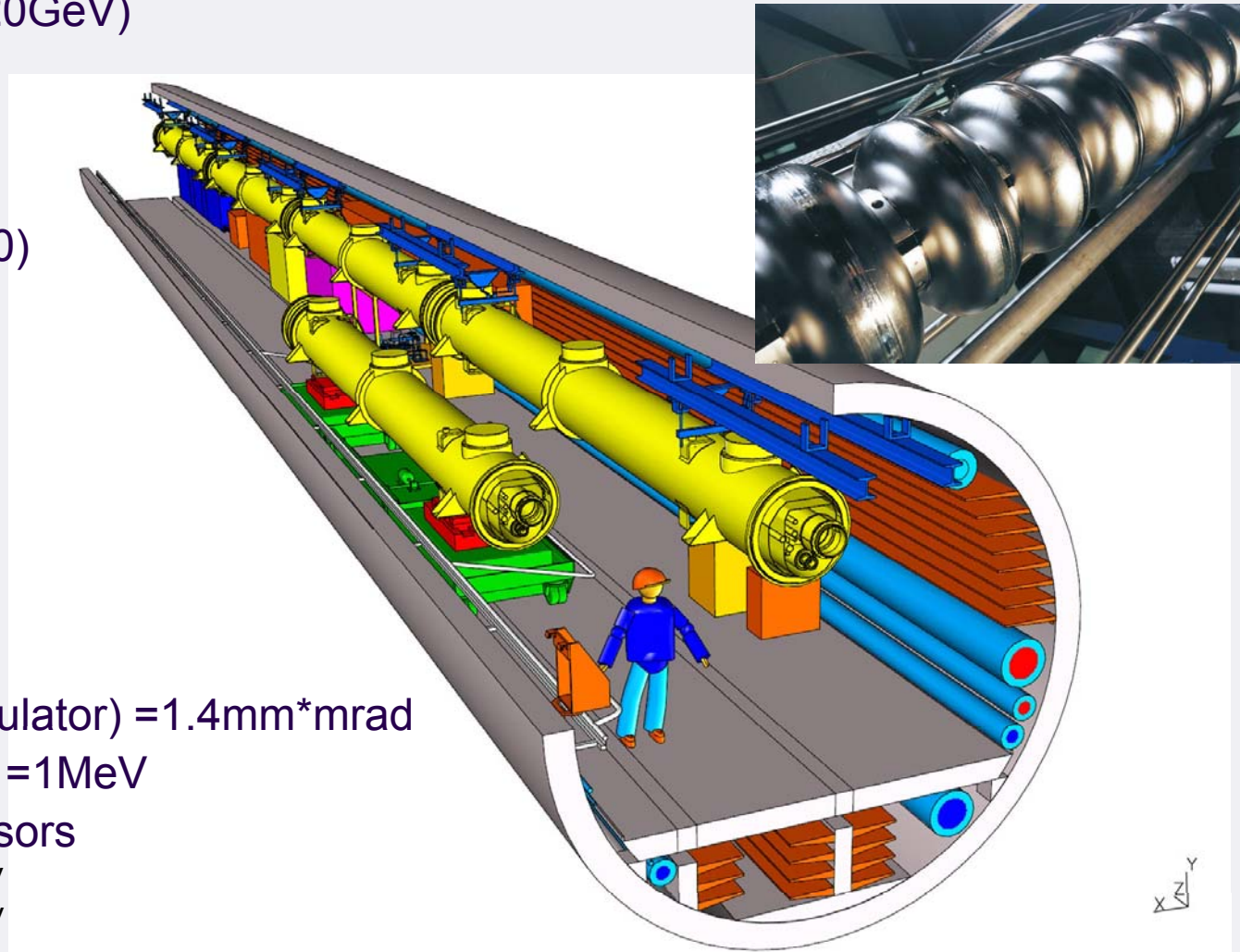
Other FEL sources: LCLS, SCSS

The XFEL Machine

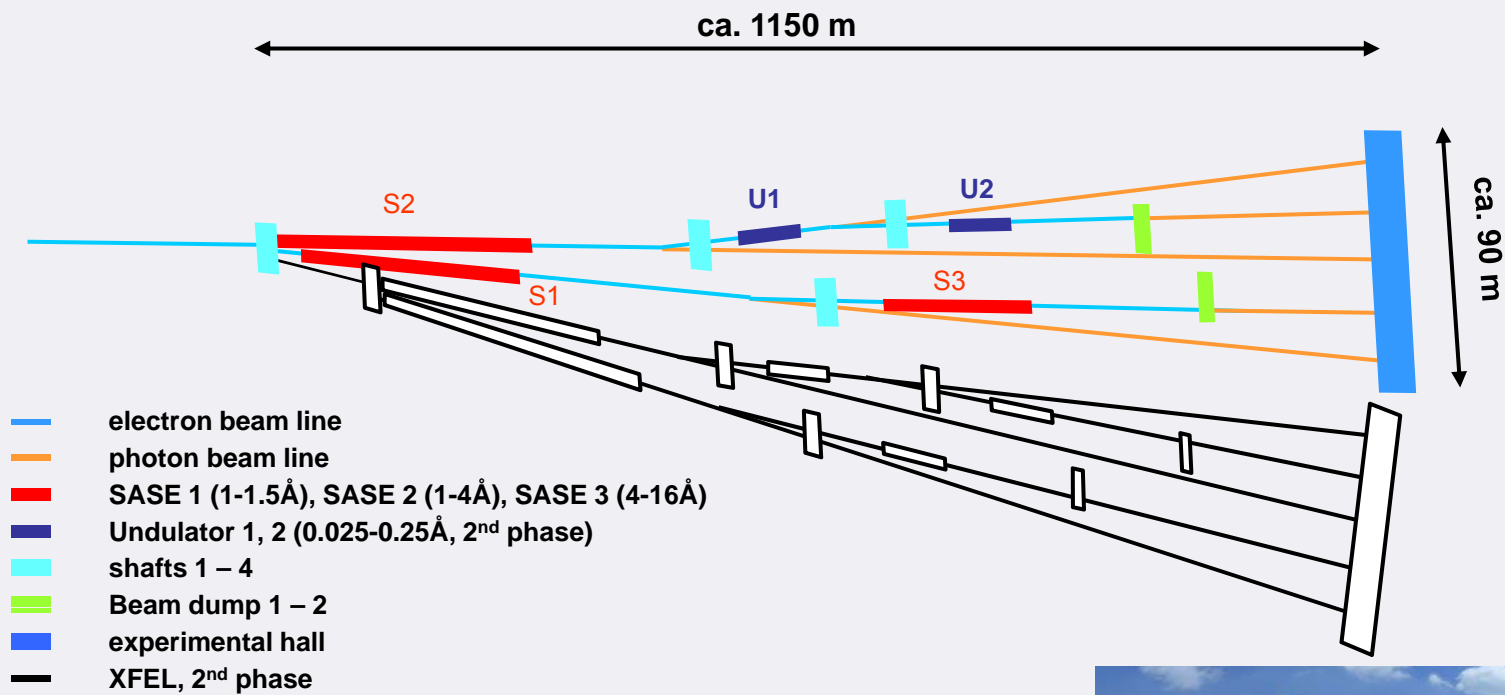


The Linac

- $W_{\max} = 17.5\text{GeV}$ (20GeV)
- $I_{\text{peak}} = 5\text{kA}$
- $Q_{\text{bunch}} = 1\text{nC}$
- $P_{\text{beam}} = 600\text{kW}$
- $N_{\text{bunch}} = 3000$ (3250)
- $E_{\text{acc}} = 23.6\text{MV/m}$
- $f_{\text{bunch}} = 5\text{MHz}$
- $f_{\text{cycle}} = 10\text{Hz}$
- 29 RF stations
- 928 cavities
- 116 modules
- $P_{\text{RF}} = 5.2\text{MW}$
- Emittance (@undulator) = $1.4\text{mm}\cdot\text{mrad}$
- ΔE (@undulator) = 1MeV
- 2 bunch compressors
 - 1/20 @0.5GeV
 - 1/5 @2.0GeV



Beam Distribution

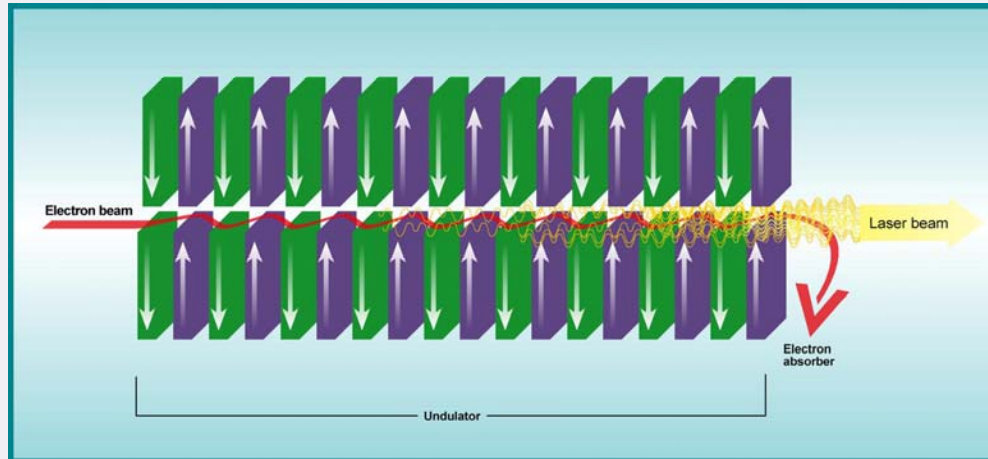


Two-stage kicker system

- Electron beam distribution among SASE undulators
- 5MHz dump kicker
 - Remove bad bunches
 - Remove bunches in the ramp phase of the flat-top kicker
- Flat-top kicker
 - Switch between S1/S3 and S2 beamlines



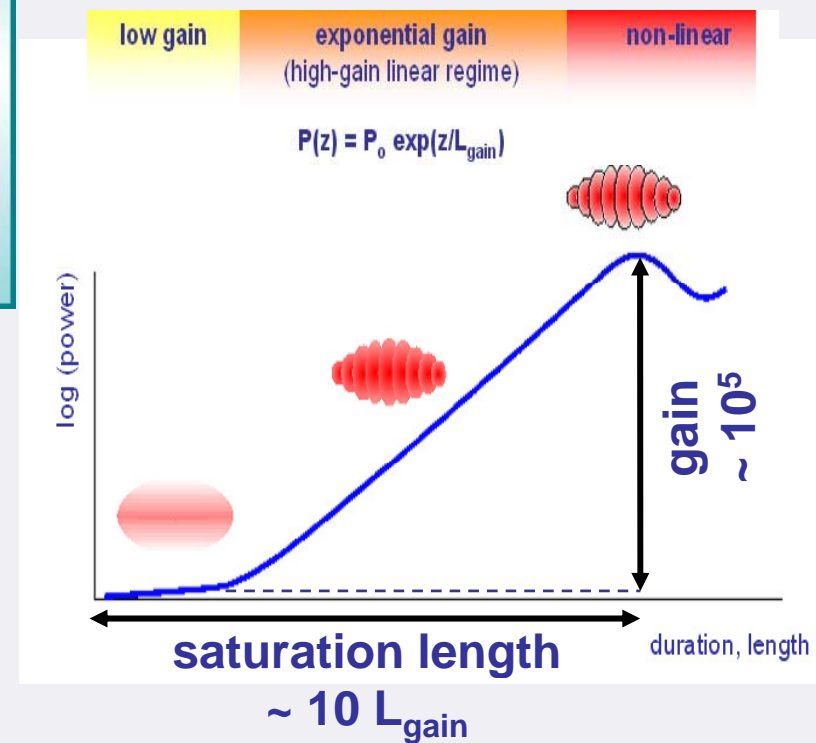
Synchrotron Radiation in FELs



- SASE principle

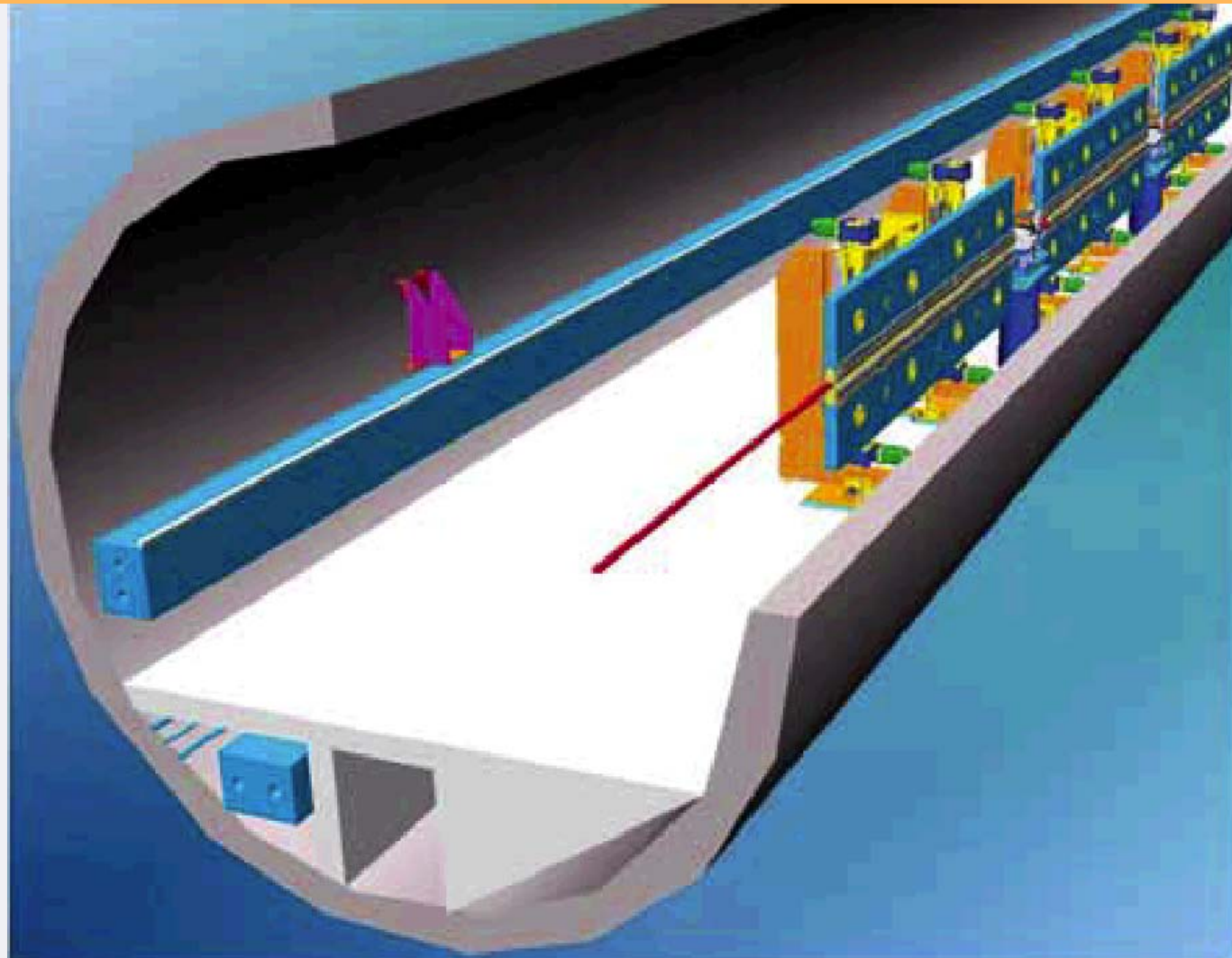
(Self-Amplified Spontaneous Emission)

- Random seed
 - Almost 100% transverse coherence
 - Limited temporal coherence
- Tail-head phenomena
 - Microbunching
 - Exponential growth of intensity & power



Undulators

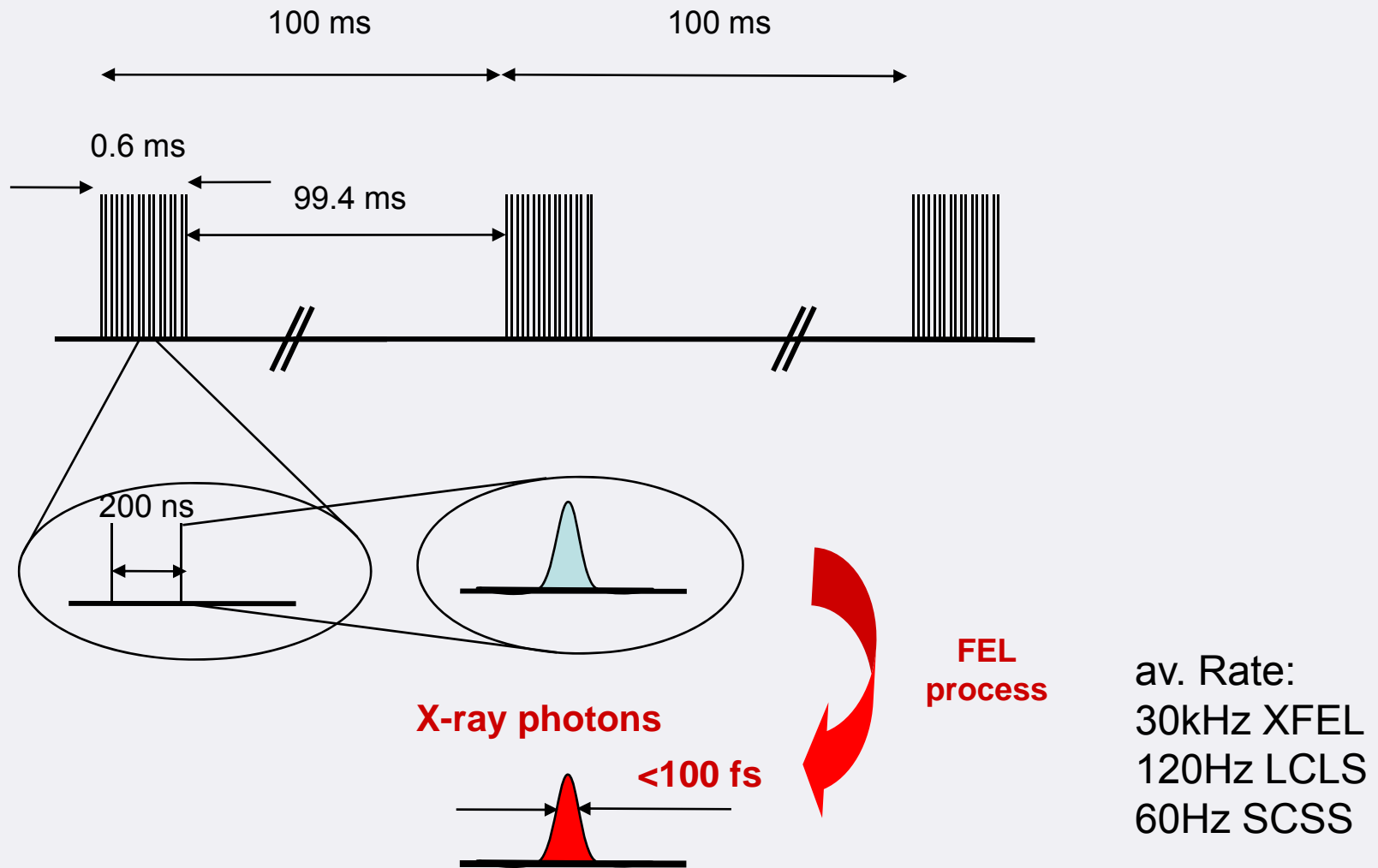
- Based on those used in FLASH
- Composed of ~5m long sections
- 21 to 42 sections per SASE source



Beamlines & Experiments

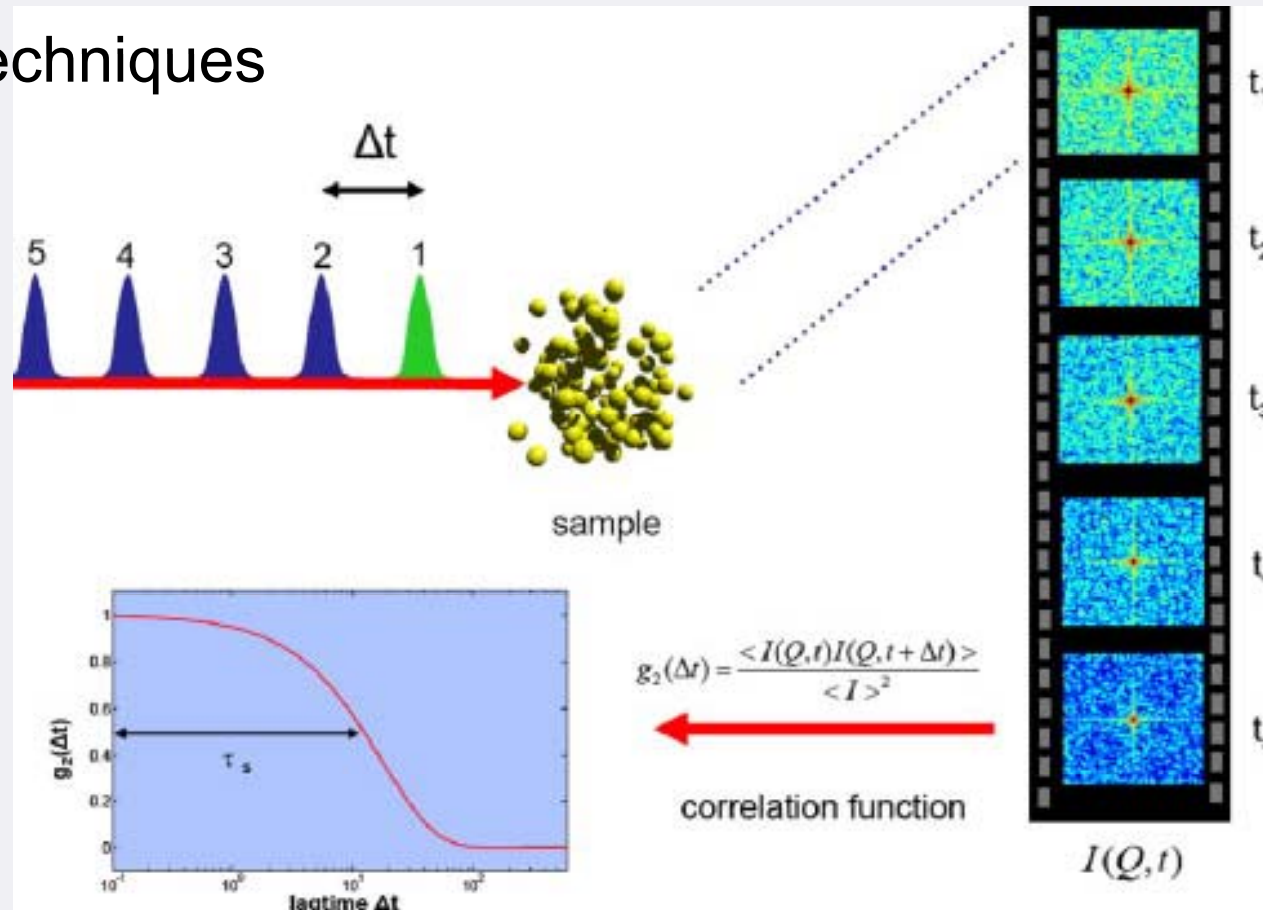
Beamline	X-ray features	Proposed instruments
SASE 1	~12 keV High coherence High flux 3 rd harmonic	PCS 1 – X-ray Photon Correlation Spectroscopy FDE 1 – Femtosecond Diffraction Experiments SPB 1 – Single Particles and Biomolecules
SASE 2	3.1 – 12.4 keV High coherence High flux	CXI 1 – Coherent X-ray Imaging HED 2 – High Energy Density XAS 2 – X-ray Absorption Spectroscopy
SASE 3	0.25 – 3.1 keV High coherence High flux 3rd harmonic	HED 1 – High Energy Density SQS 1 – Small Quantum Systems XAS 1 – X-ray Absorption Spectroscopy SQS 2 – Small Quantum Systems PCS 2 – X-ray Photon Correlation Spectroscopy CXI 2 – Coherent X-ray Imaging

The Linac: Time Structure



X-ray Photon Correlation Spectroscopy

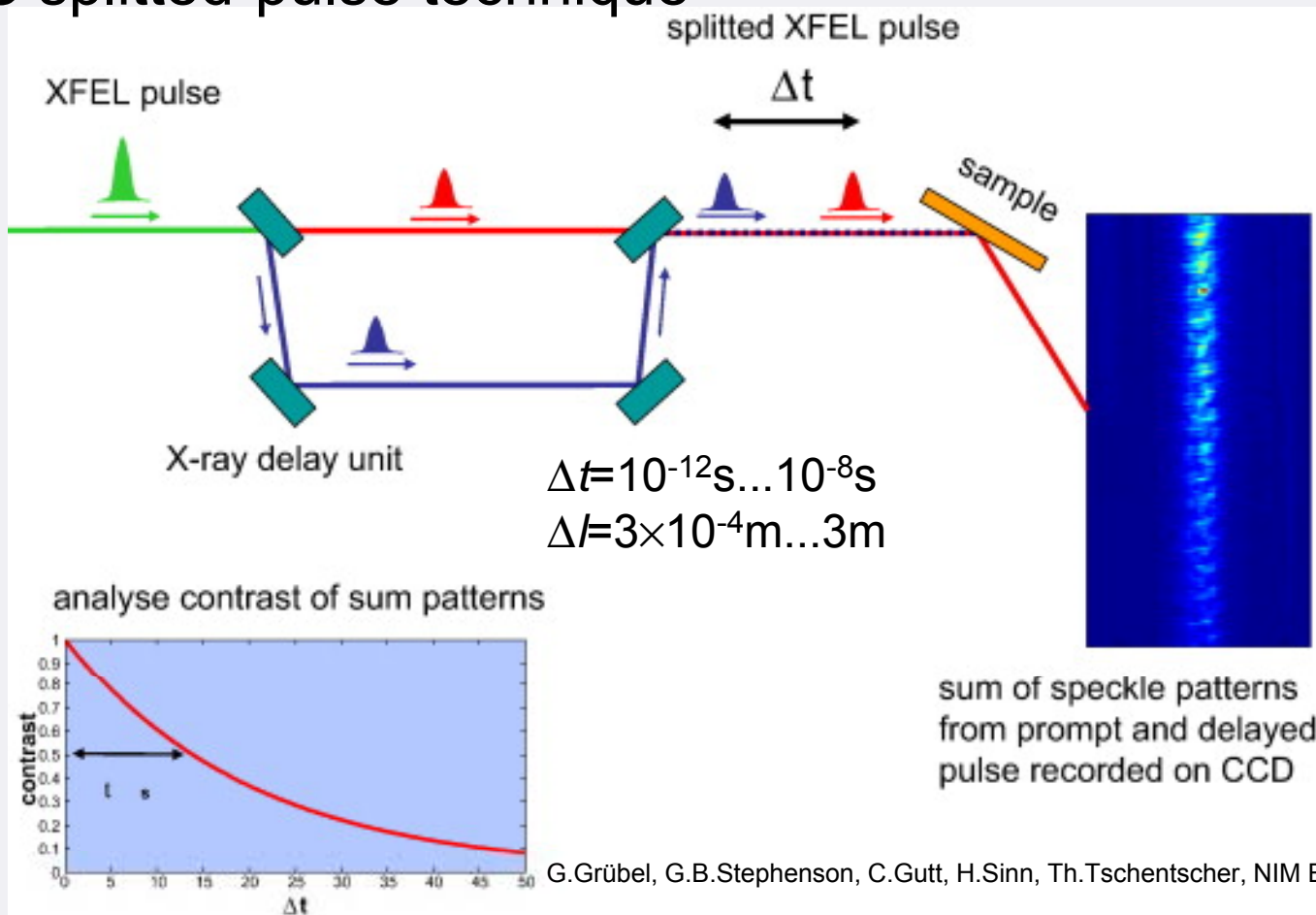
XPCS techniques



G.Grübel, G.B.Stephenson, C.Gutt, H.Sinn, Th.Tschentscher, NIM B 262 (2007)357 –367

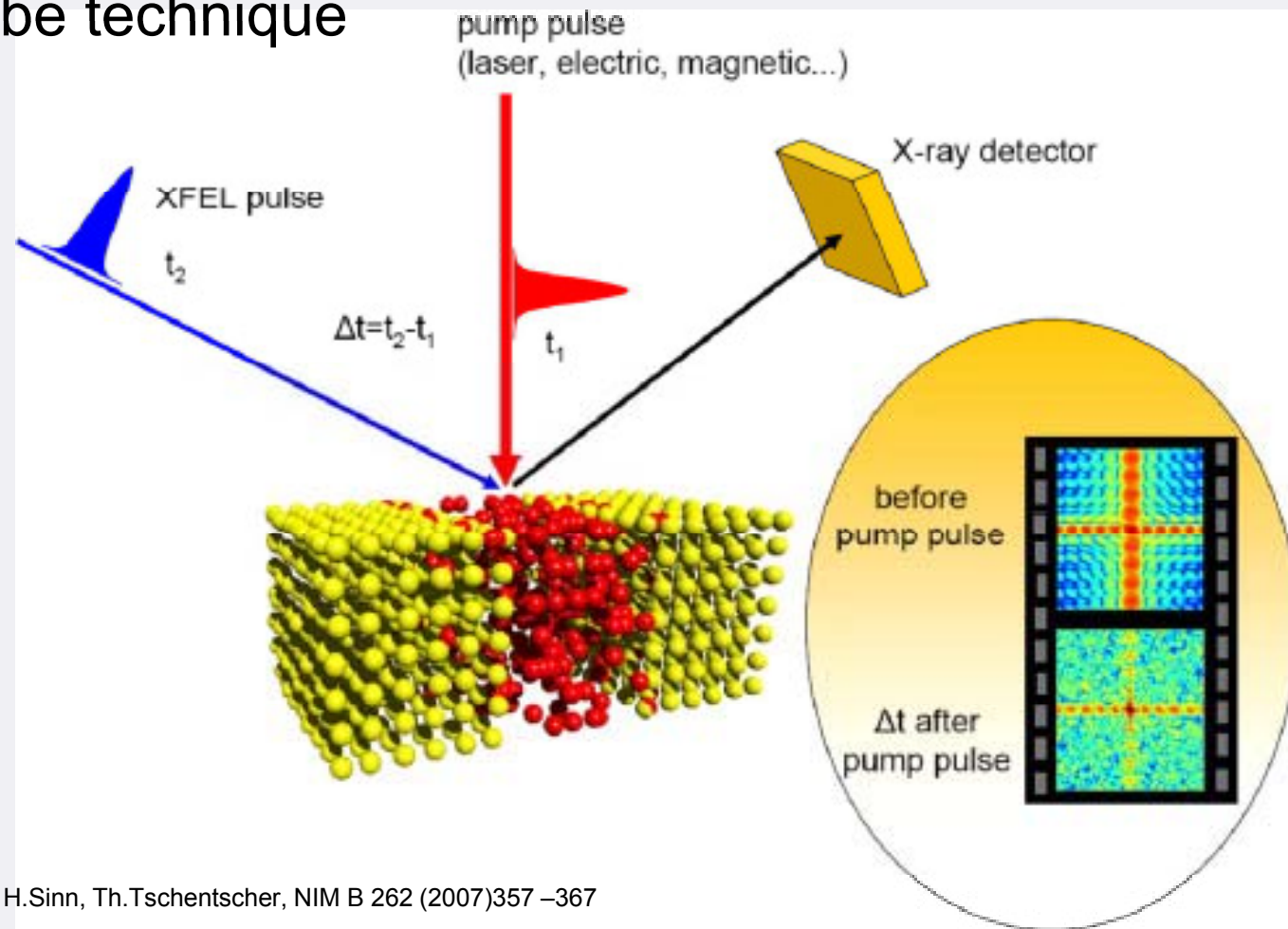
X-ray Photon Correlation Spectroscopy

XPCS splitted-pulse technique



X-ray Photon Correlation Spectroscopy

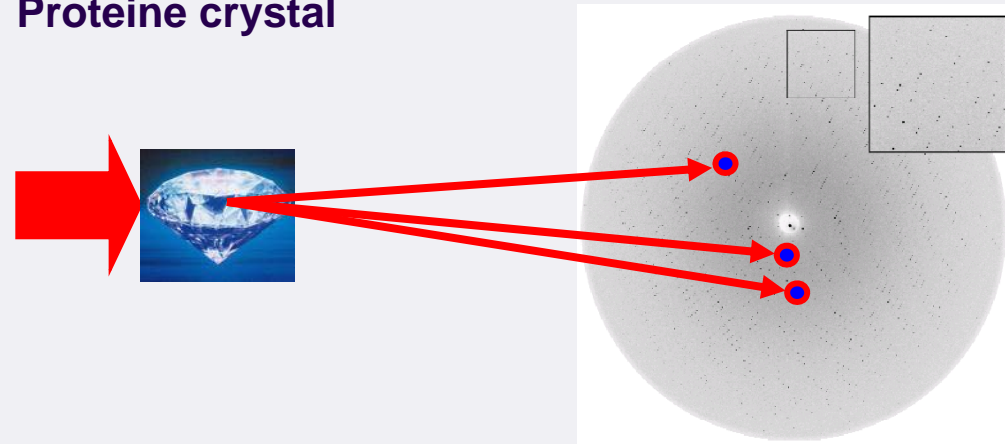
XPCS pump-probe technique



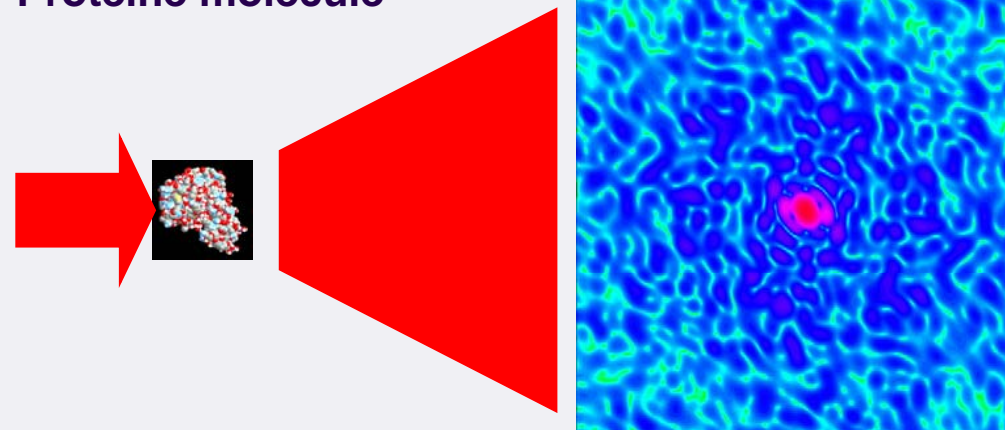
G.Grübel, G.B.Stephenson, C.Gutt, H.Sinn, Th.Tschentscher, NIM B 262 (2007)357 –367

Single Molecules & Coherent X-ray Imaging

Proteine crystal



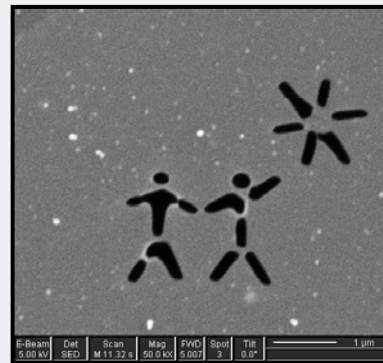
Proteine molecule



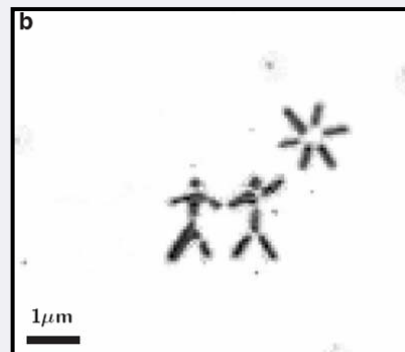
(Simulated images)

Single Molecules & Coherent X-ray Imaging

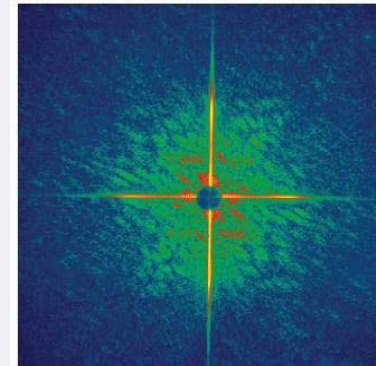
TEM picture
of original structure



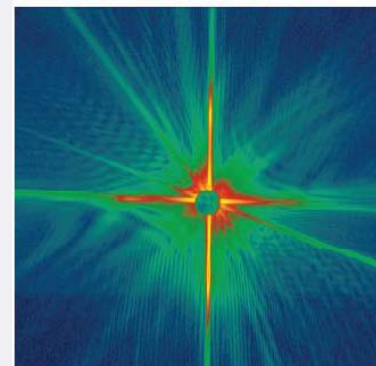
Reconstructed picture



FLASH (32nm 25fs 10^{14} W/cm²)



Diffraction pattern
from first pulse

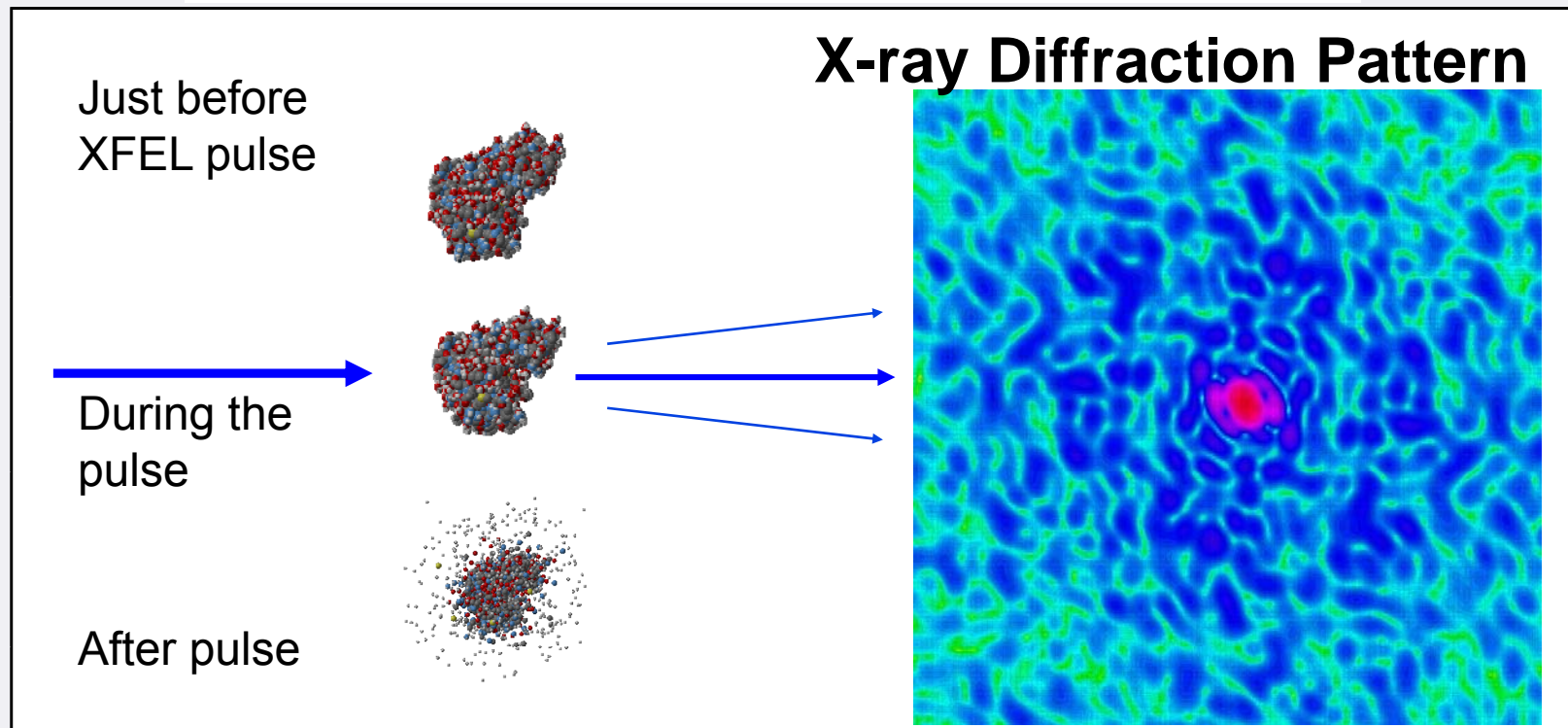


Diffraction pattern
From second pulse

H. Chapman, J. Hajdu et al.

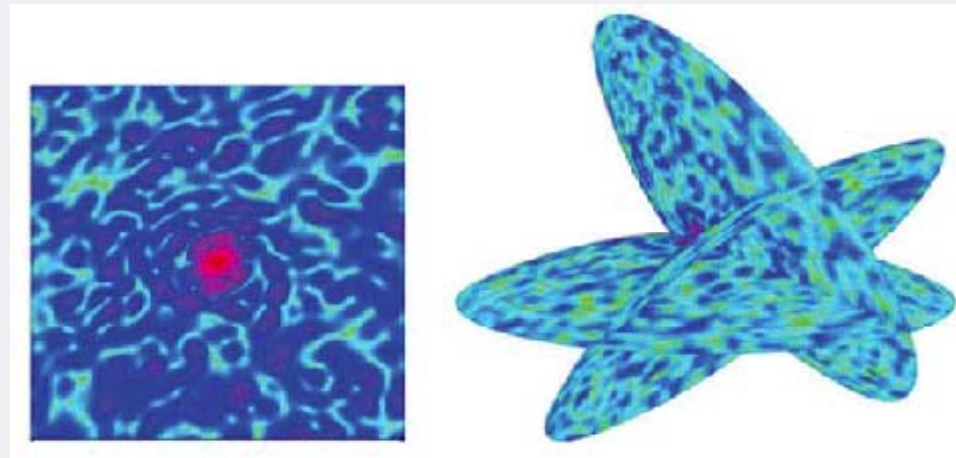
Single Molecules & Coherent X-ray Imaging

Single Molecule Imaging



Henry Chapman, *DESY*
Janos Hajdu, *Uppsala University and Stanford*

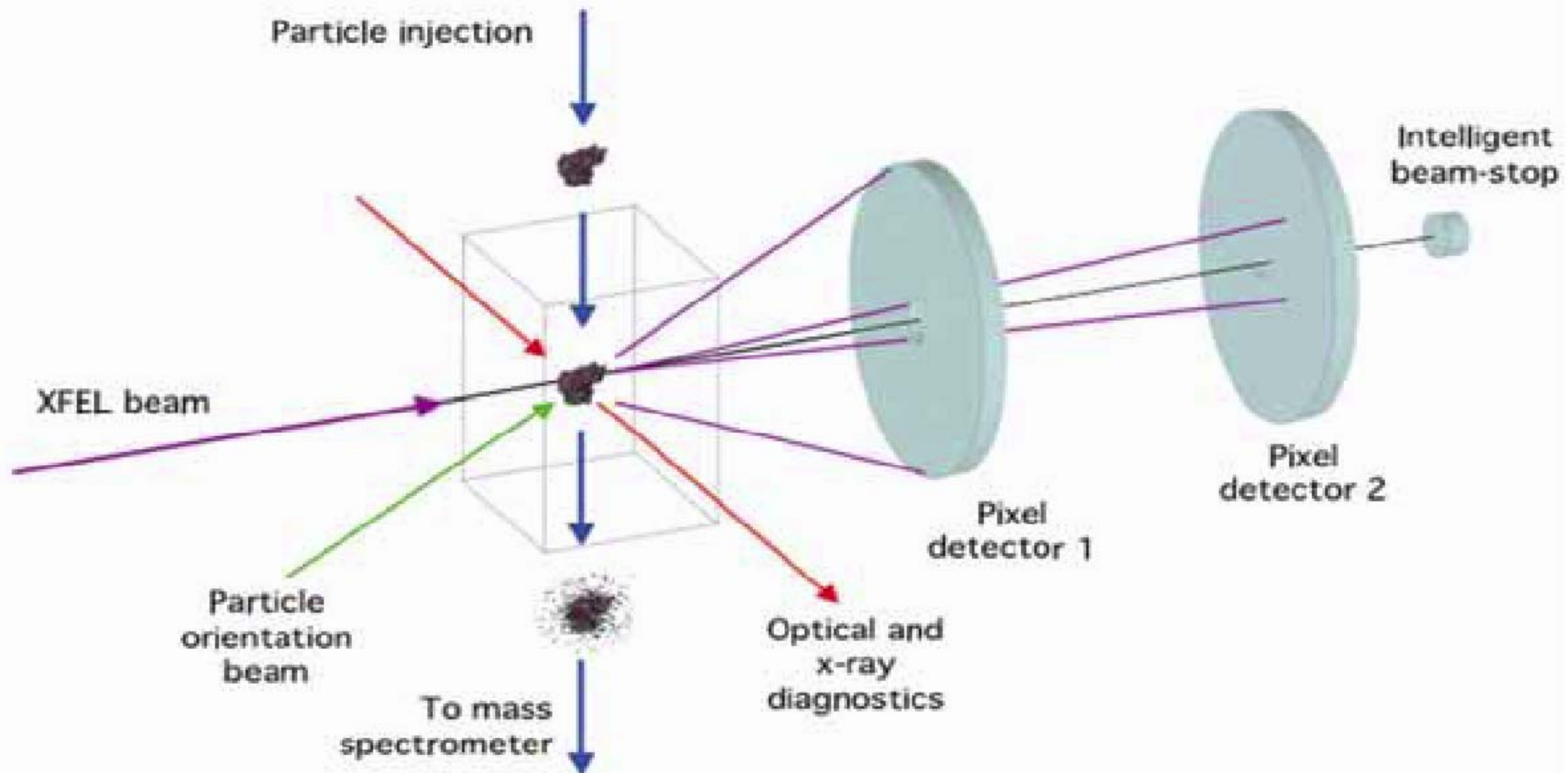
Single Particles & Coherent X-ray Imaging



**Aligning the patterns along common axis allows full
3D reconstruction of the molecule**

Single Particles & Coherent X-ray Imaging

Experimental setup



XFEL Detector Challenges

Time structure of the photon signals

High radiation dose at small angles: 10^4 photons per pixel per shot

→ over 3 years **1 GGy**

- Radiation damage of silicon sensor
- Radiation damage of underlying electronics

→ Program for radiation damage studies needed

High radiation dose at specific pixels: 10^5 photons in $10\mu\text{m} \times 10\mu\text{m}$
("charge explosion")

- 10^5 photons of 12 keV create: $(10^5 \times 12 \times 10^3) / 3.6 =$

3×10^8 electron-hole pairs

→ "plasma effect" gives shielding of drift field

→ diffusion before drift

→ peak broadening (space and time).

Despite that, three consortia (DEPFET-APS, HPAD, LPD) took up the challenge to build pixel detectors for the XFEL

XFEL Detector Requirements

- Energy 0.8..15keV
- No energy resolution
- High efficiency (>0.8)
- High dose 1GGy/3a
- Low dead area <10%
- High dynamic range
- XFEL Timing compliant
- Low noise (<1 ph)
- Low crosstalk
- Vaccum compatible
- Central hole

	PPnX	PPX	CDI	SPI	XPCS
E (keV)	6–15	12	0.8-12	12.4	6 – 15
$\Delta E/E$	No	No	No	No	No
QE	>0.8	>0.8	>0.8	>0.8	>0.8
Rad Tol	10^{16} ph	10^{16} ph	2×10^{16} ph	2×10^{15} ph	2×10^{14} ph
Size	200 deg	120 deg	120 deg	120 deg	0.2 deg
Pixel	7 mrad	100 μ m	0.1 mrad	0.5 mrad	4 μ rad
# pixels	500 \times 500	3k \times 3k	20k \times 20k	4k \times 4k	1k \times 1k
tiling	<20%	<10%	See text		<20%
L Rate	5×10^4	3×10^6	10^5	10^4	10^3
G Rate	3×10^7	10^7	10^7	10^7	10^6
Timing	10Hz	10Hz	5MHz	10Hz	5MHz
Flat F	1%	1%	1%	1%	1%
Dark C	<1 ph	<1 ph	<1 ph	<1 ph	<1 ph
R Noise	<1 ph	<1 ph	<1 ph	<1 ph	<1 ph
Linearity	1%	1%	1%	1%	1%
PSF	1 pixel	100 μ m	1 pixel	1 pixel	1 pixel
Lag	10^{-3}	10^{-3}	7×10^{-5}	10^{-3}	10^{-3}
Vacuum	No	No	Yes	Yes	No
Other	Hole	Hole			Hole

XFEL Detector Concepts

	DEPFET-APS	LPD	HPAD
# Pixels	1k × 1k	1k × 1k	1k × 1k
Pixel size	200μm × 200μm	500μm × 500μm	200μm × 200μm
Sensor	DEPFET array	Si-pixel	Si-pixel
Dynamic range	>10 ⁴ ph	2 × 10 ⁴ ph (10 ⁵ ph)	2 × 10 ⁴ ph
Noise	~15 × 10 ⁻³ ph ~50e	0.21ph (0.93ph) 700e (3100e)	~45 × 10 ⁻³ ph ~150e
Concept	DEPFET nonlinear gain compression Per-pixel ADC	Multiple gain paths On-chip ADC	Adaptive gain switching (preset gain option)
Storage	8bit DRAM	3-fold analogue	2bit digital + analogue
Storage depth	≥256	512	>200
Challenges	Linearity & calibration In-pixel ADC DRAM refresh Power budget Pixel area	Preamplifier: noise, dynamic range & PSRR Feedback discharge Analogue storage	Dynamic gain switching Charge injection Analogue storage Pixel area
Radiation hardness			

XFEL Detectors: Obstacles, Difficulties & Challenges

Common Issues:

Droop due to leakage of

- Capacitors
 - Tunneling of electrons
- Switches (FETs)
 - Short-channel effects
 - Tunneling of electrons

Radiation hardness

CMOS Technology

IBM cmrf8sf DM (130nm CMOS)

- Proposed by all 3 XFEL 2D detector consortia
- De-facto standard for LHC upgrades
 - Choice mainly based on excellent experience with cmos6sf (0.25 μ m) technology
- Proven radiation hardness >10Mrad
- Foundry access via CERN as a second source besides MOSIS
- Long-term availability
- Permits sufficiently high integration density
- (dual) MIMCAPS can be employed as a (fallback) solution for storage caps

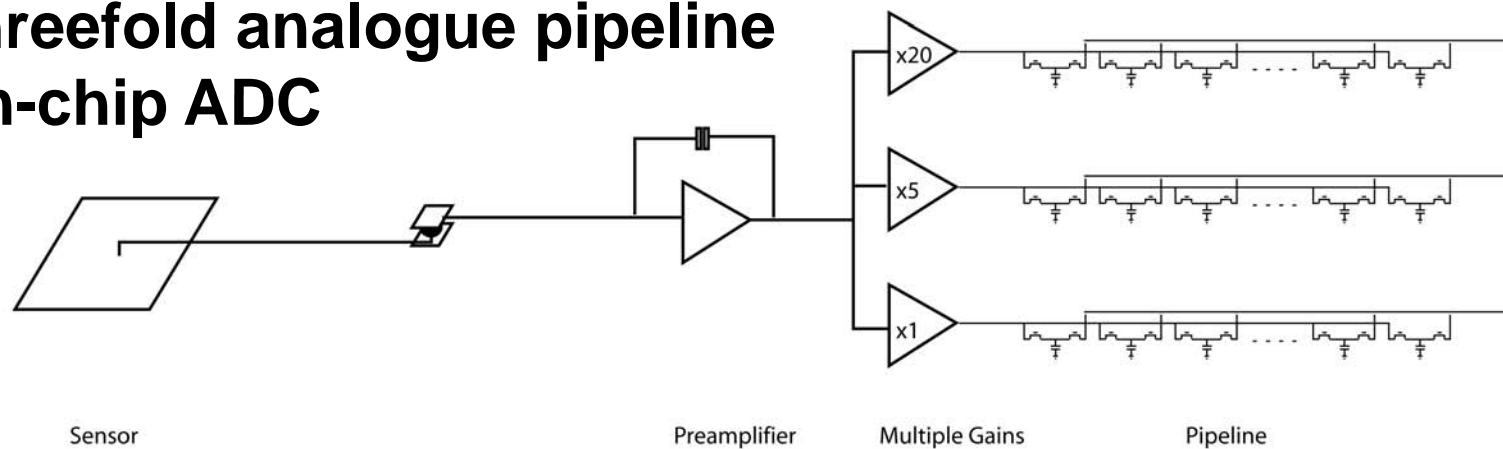
All 3 projects agreed on this technology and will share the development of some common blocks like LVDS IOs, enclosed std. cells etc.

The Large Pixel Detector (LPD) Project (STFC)

Multi-Gain Concept

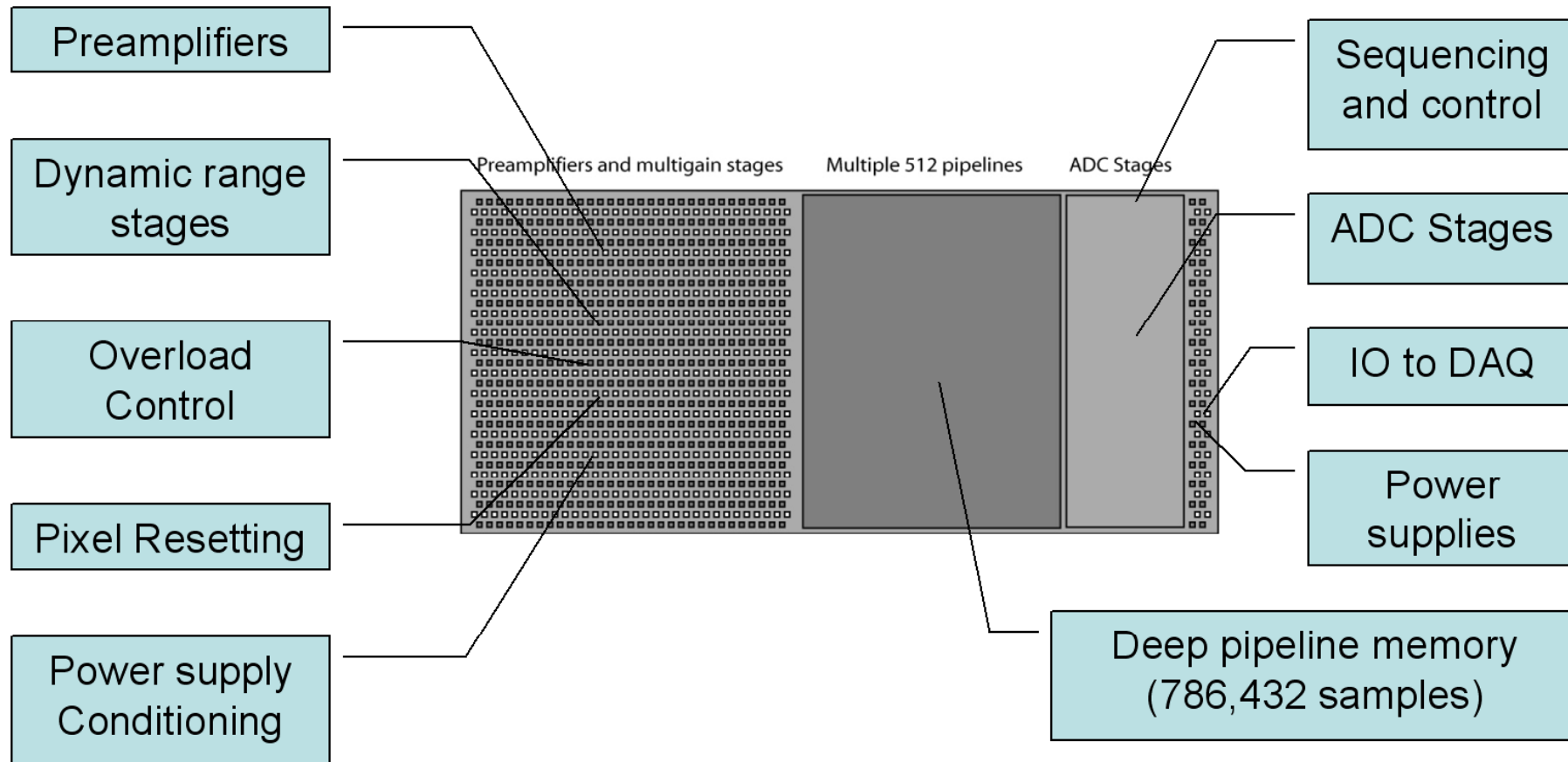
Dynamic Range Compression required
Experience with calorimetry at CERN
Relaxes ADC requirements
Fits with CMOS complexity

Threefold analogue pipeline On-chip ADC



(M. French, STFC)

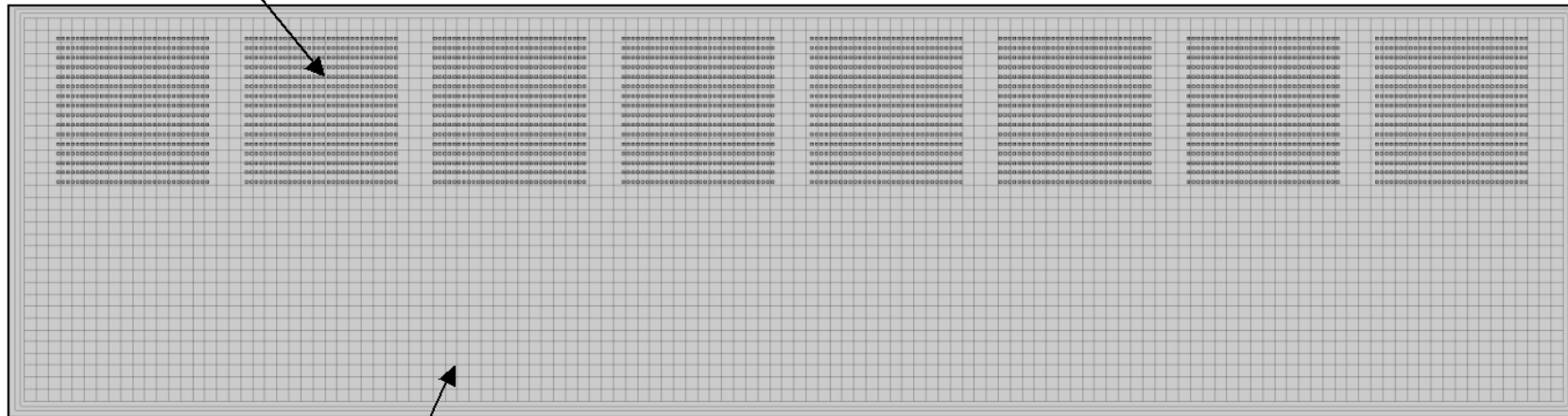
LPD Chip Layout (STFC)



(M. French, STFC)

LPD Sensor Layout (STFC)

ASIC
interconnect
pads



0.5mm pixels

(M. French, STFC)

The Large Pixel Detector (LPD) Project (STFC)

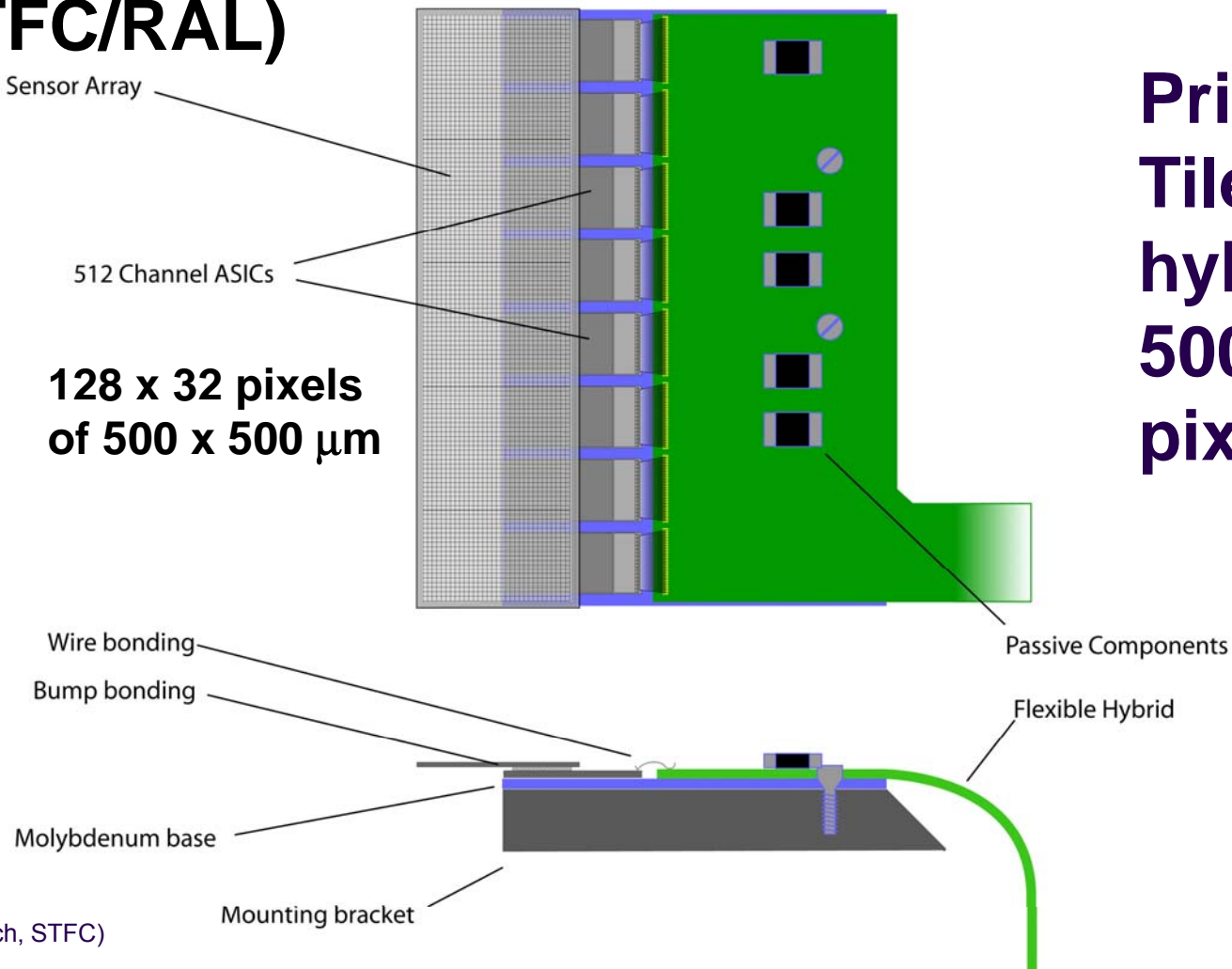
(STFC/RAL)

0.5mm Sensor Array

512 Channel ASICs

**128 x 32 pixels
of 500 x 500 μm**

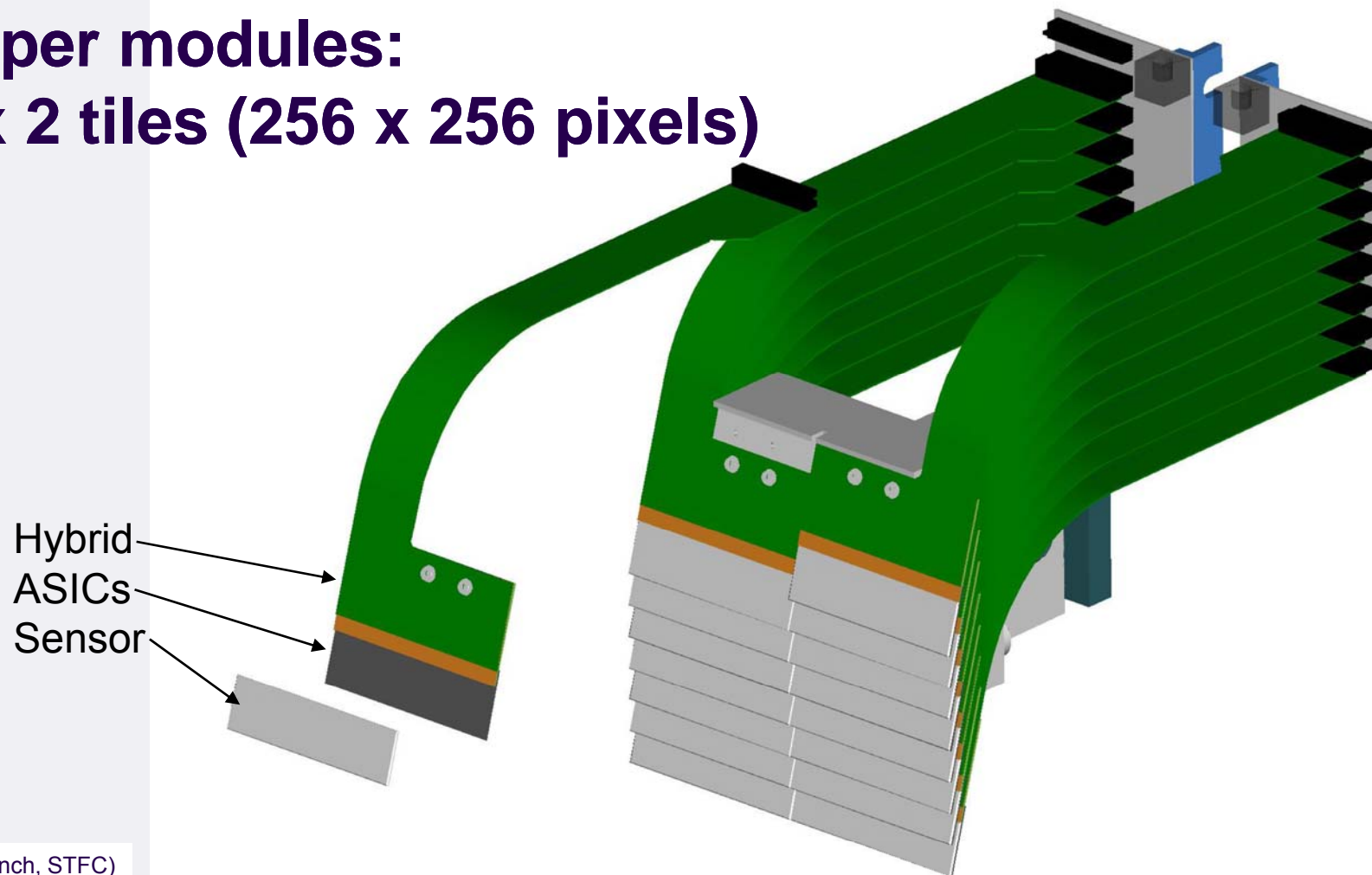
**Principle:
Tiled
hybrid with
500 μm
pixels**



(M. French, STFC)

The Large Pixel Detector (LPD) Project (STFC)

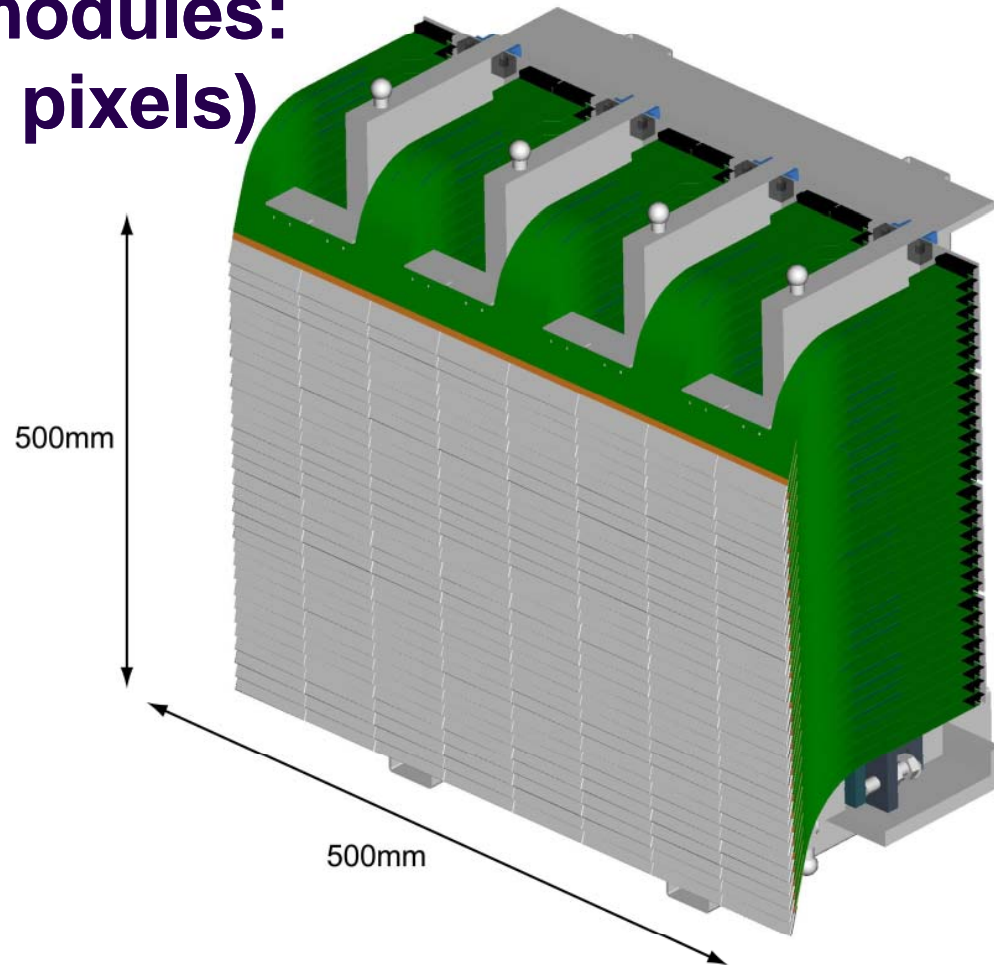
**Super modules:
8 x 2 tiles (256 x 256 pixels)**



(M. French, STFC)

The Large Pixel Detector (LPD) Project (STFC)

**4 x 4 Super modules:
(1024 x 1024 pixels)**

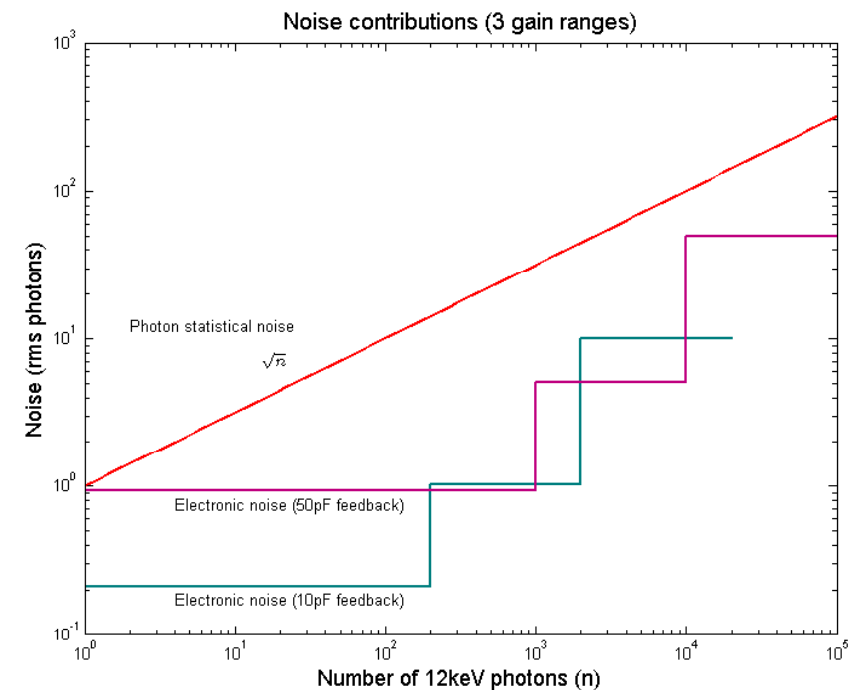


(M. French, STFC)

LPD Noise & Gain (STFC)

Pre-amplifier feedback capacitor	10pF			50pF		
Gain factor	100	10	1	100	10	1
Dynamic Range (12keV photons)	2×10^2	2×10^3	2×10^4	10^3	10^4	10^5
Pre-amp noise	0.13	0.13	0.13	0.47	0.47	0.47
Gain-stage noise	0.13	0.19	-	0.63	0.99	-
Pipeline noise (100fF storage)	0.038	0.38	3.8	0.19	1.9	19
ADC noise (12-bit resolution)	0.092	0.92	9.2	0.46	4.6	46
Total noise	0.21	1.02	9.95	0.93	5.1	50

Simulation for different
Feedback caps

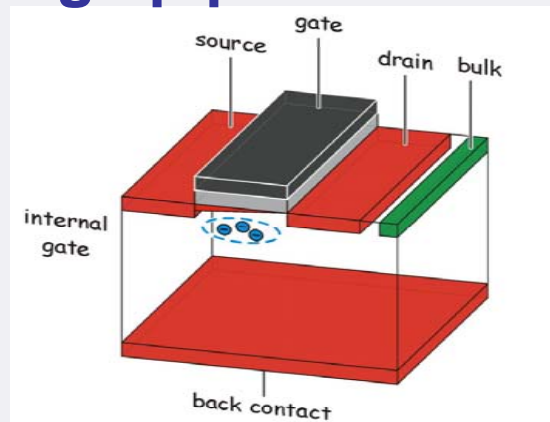


(M. French, STFC)

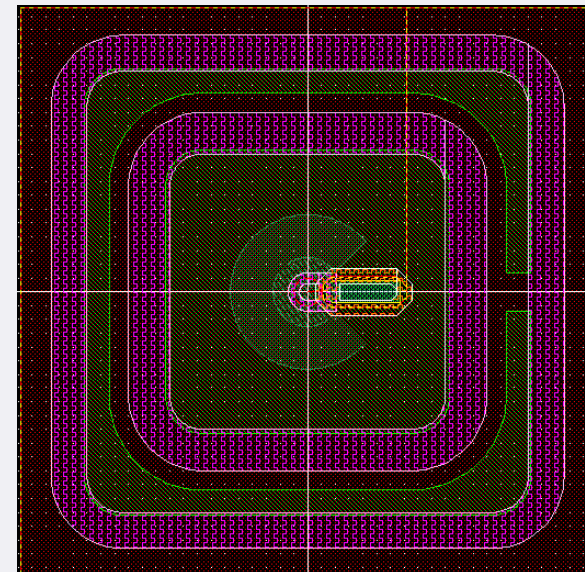
DEPFET Active Pixel Sensor Detector (MPI-HLL)

- DEPFET per pixel
- Very low noise (good for soft X-rays)
- non linear gain (good for DR)
- per pixel ADC
- digital storage pipeline

MPI-HLL, Munich
Universität Heidelberg
Universität Siegen
Politechnico di Milano
Università di Bergamo
DESY, Hamburg

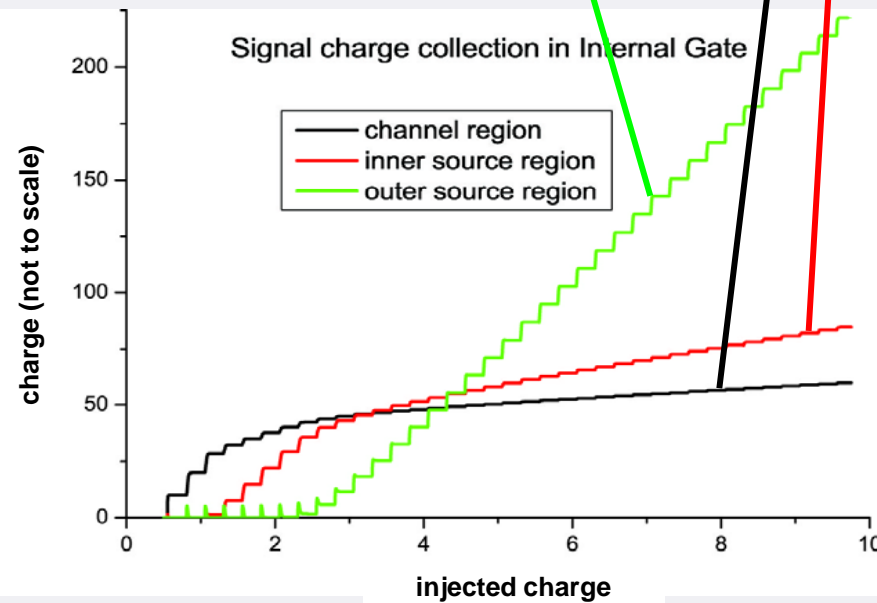
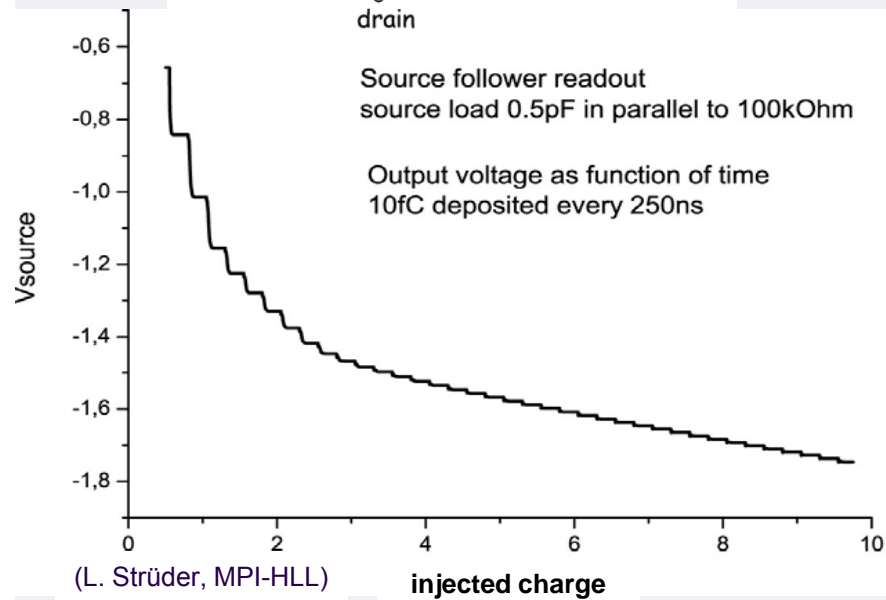
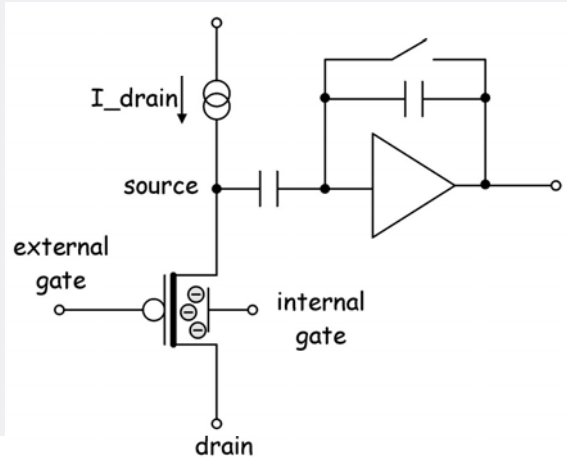


200 μm x 200 μm pixel combines DEPFET
with small area drift detector (scaleable)



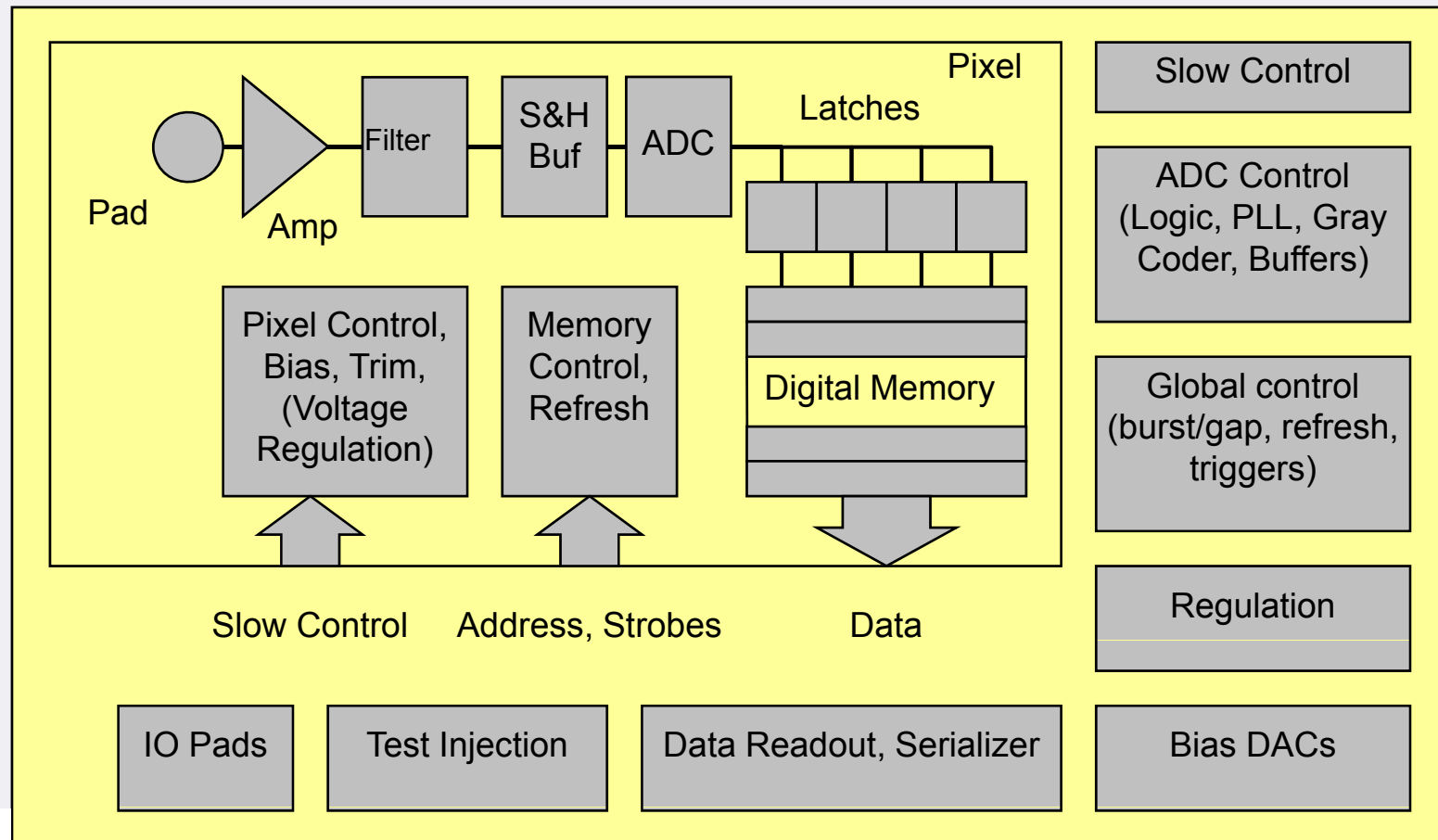
(L. Strüder, MPI-HLL)

DEPFET Nonlinear Gain (MPI-HLL)



DEPFET Active Pixel Sensor Detector (MPI-HLL)

Block Diagram



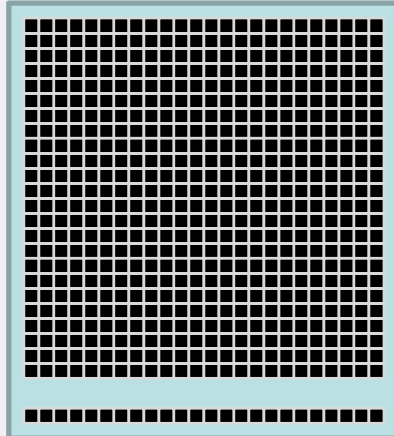
(L. Strüder, MPI-HLL)

DEPFET Active Pixel Sensor Detector (MPI-HLL)

Dynamic range challenge is relaxed by non-linear sensor characteristics

Baseline approach:

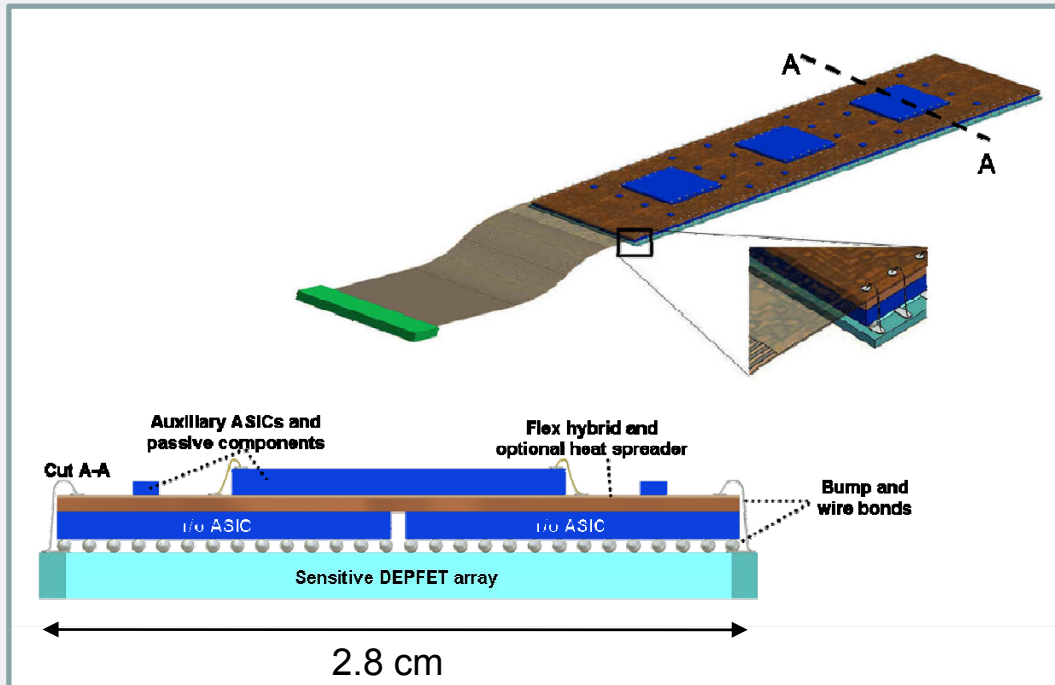
- **Double correlated Sampling** (read voltage or current, tbd.)
- **ADC** in every pixel (200ns, 8Bit)
- **Digital storage** in every pixel (DRAM w. refresh)
- Serial digital readout during bunch gaps



(L. Strüder, MPI-HLL)

Key Parameters of readout ASIC	
Pixel Size	200 × 200 μm ²
Number of pixels	64 × 64 = 4096
Chip size	~ 13 × 14 mm ² , IO pads on one side
Amplification	Double corr. sampling, SF or current RO
Target noise	50 electrons
Target power per pixel	1 mW (0.01mW w. power cycling)
Digitization	per pixel, ~ 8 bit
storage	digital, per pixel, 256-512 events
trigger selection	Yes
readout	serial, daisy chain of several chips

DEPFET Active Pixel Sensor Detector (MPI-HLL)

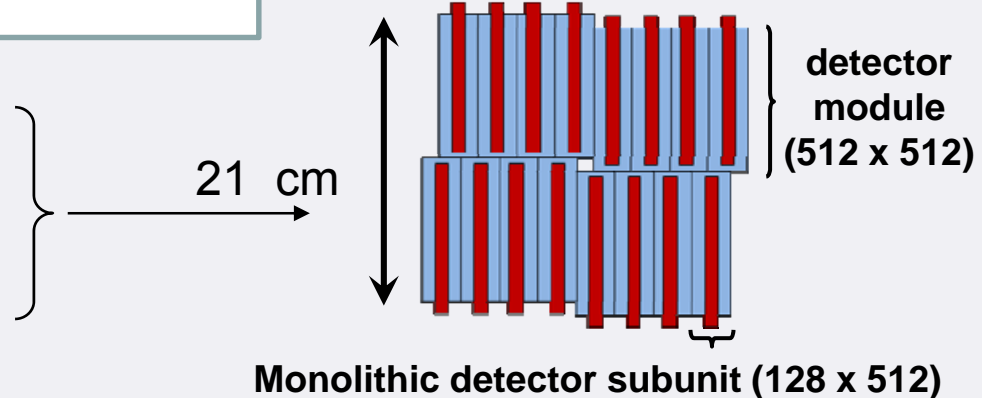


Multi Chip Modules

- DEPFET Sensor bump bonded to Readout ASICs
- Optional Heat spreader
- Flex Hybrid with passive components and auxiliary ASICs (e.g. voltage regulators)
- Sensor (512x128 pixels)
2.56x10.24 cm²
- 16 readout ASICs (64x64)
- Dead area: 10-15%

- connect detector units to **ladder**
- 1 ladder = 128x 512 pixels
- 4 ladders = 1 quadrant
- 4 quadrants = **1k x 1k detector**

(L. Strüder, MPI-HLL)



Hybrid Pixel Array Detector (HPAD) (DESY)

Basic parameters

- Single shot 2D-imaging
- 200 μm x 200 μm pixels
- 5 MHz framing speed
- Single photon sensitivity at 12keV
- 2×10^4 dynamic range, using 3 switched gains
- >200 images storage depth
- 128 x 256 monolithic tiles
- Flat detector

The HPAD consortium:

PSI/SLS -Villingen: chip design; interconnect and module assembly

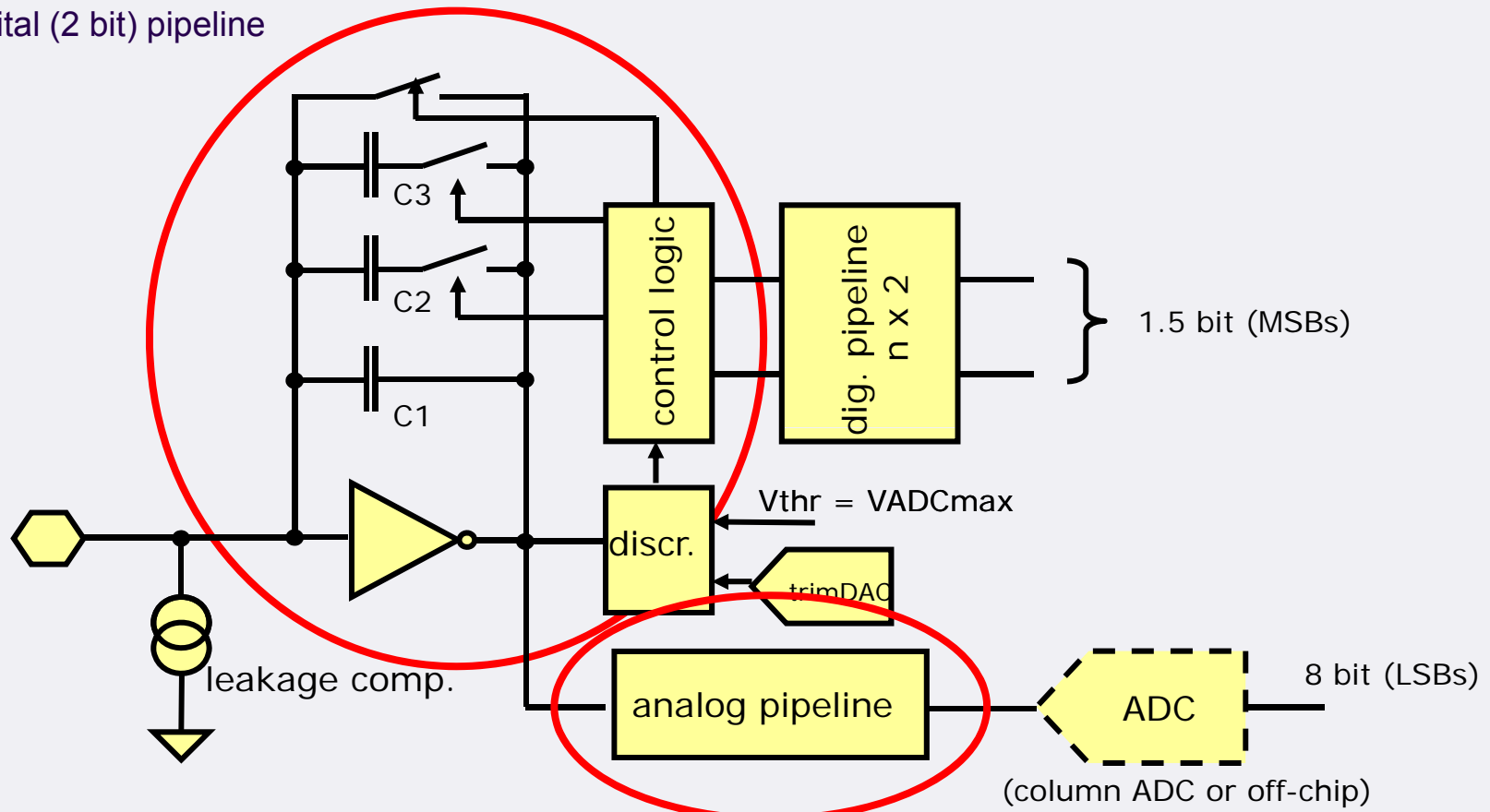
Universität Bonn: chip design

Universität Hamburg: Radiation damage tests, “charge explosion” studies; and sensor design

DESY-Hamburg: chip design, interface and control electronics, mechanics; overall coordination

Hybrid Pixel Array Detector (HPAD) Concepts (DESY)

- wide dynamic input range
- multiple (3) scaled feedback capacitors
- reduced ADC resolution (10 bit instead of 12 bit)
- analog + digital (2 bit) pipeline



HPAD Dynamic Range (DESY)

Integrator gain requirements:

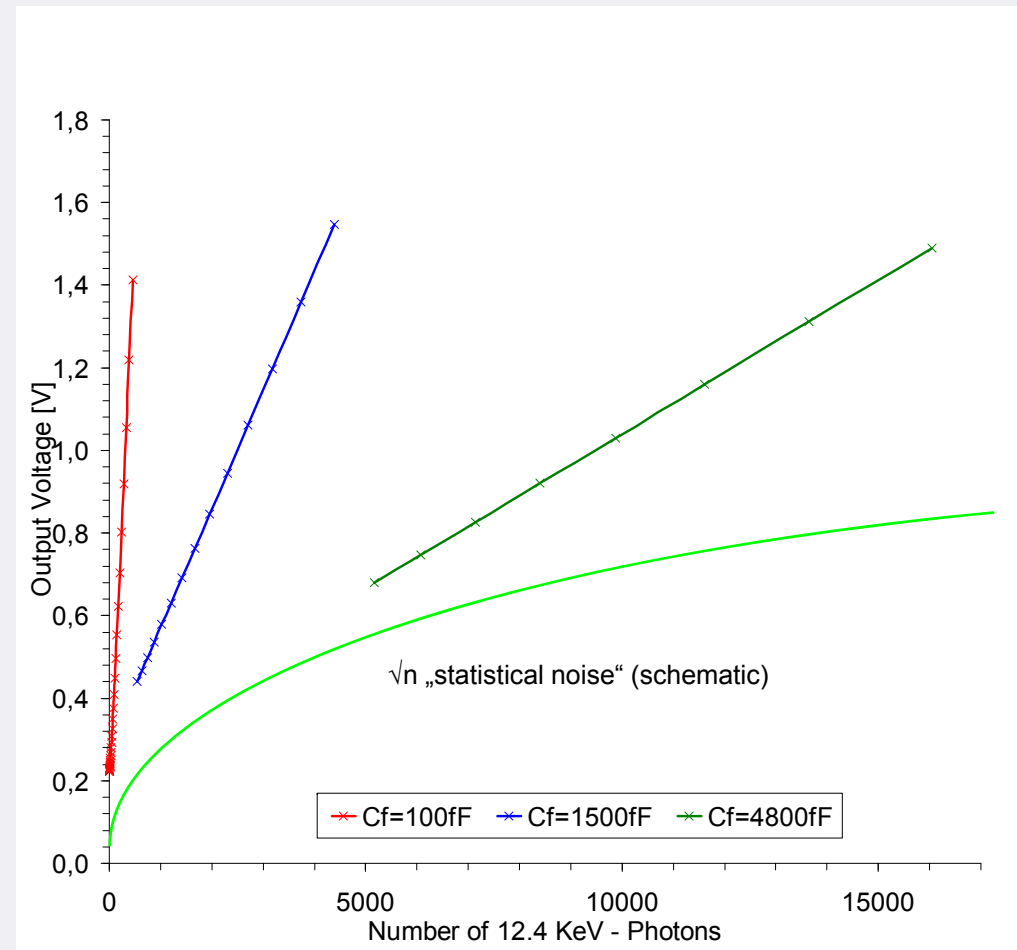
Effective analog resolution ≥ 8 bit

Analogue resolution always better than

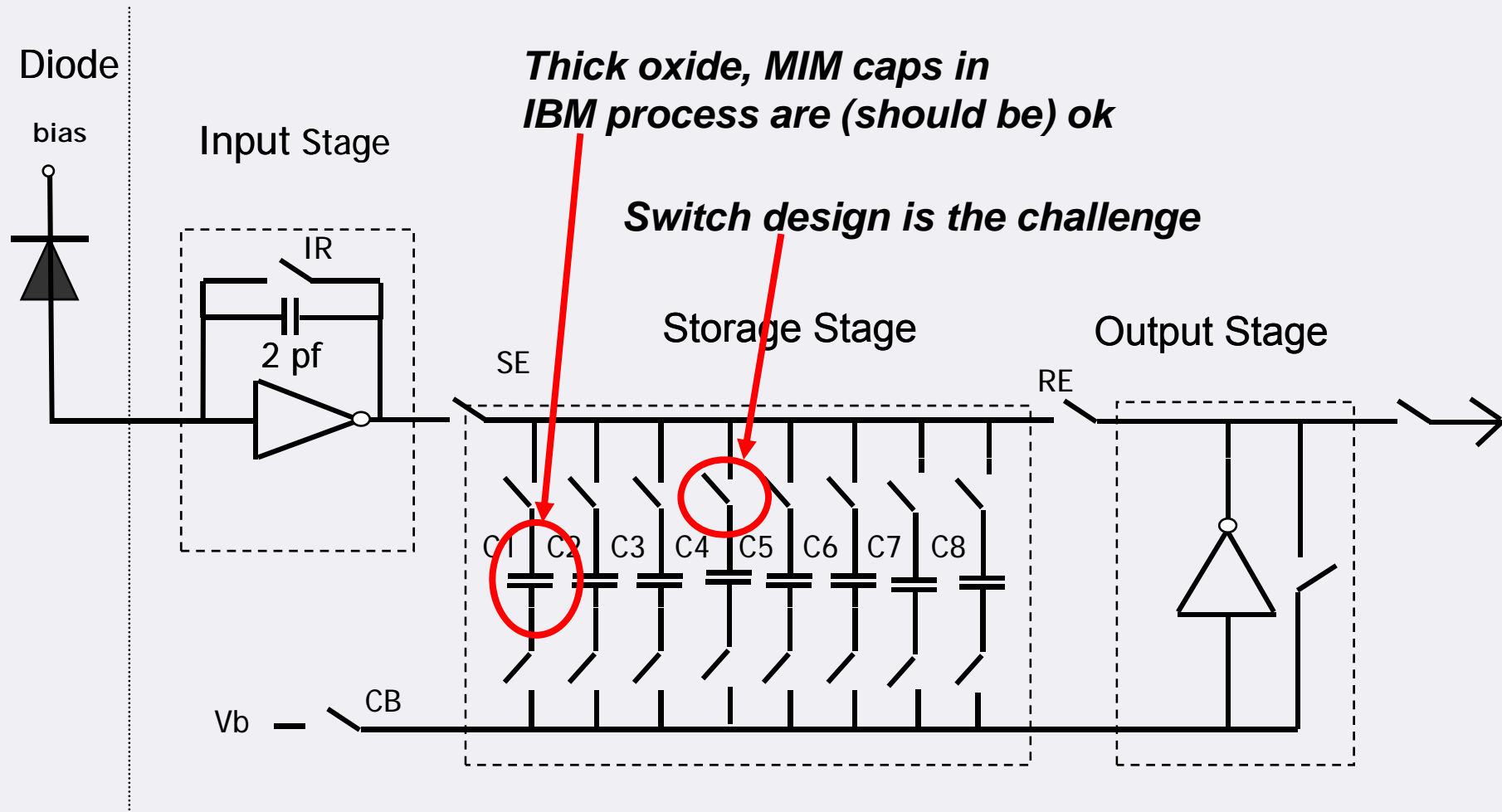
“statistical noise” $\sqrt{n_{ph}}$

maximum signal $\geq 10^4$ photons

range	norm. gain	Cf [fF]	max n_{ph}
1	1	100	256
2	1/16	1600	4096
3	1/64	6400	16384



100 msec "loss free" Charge Storage in Analogue Pipeline (DESY)



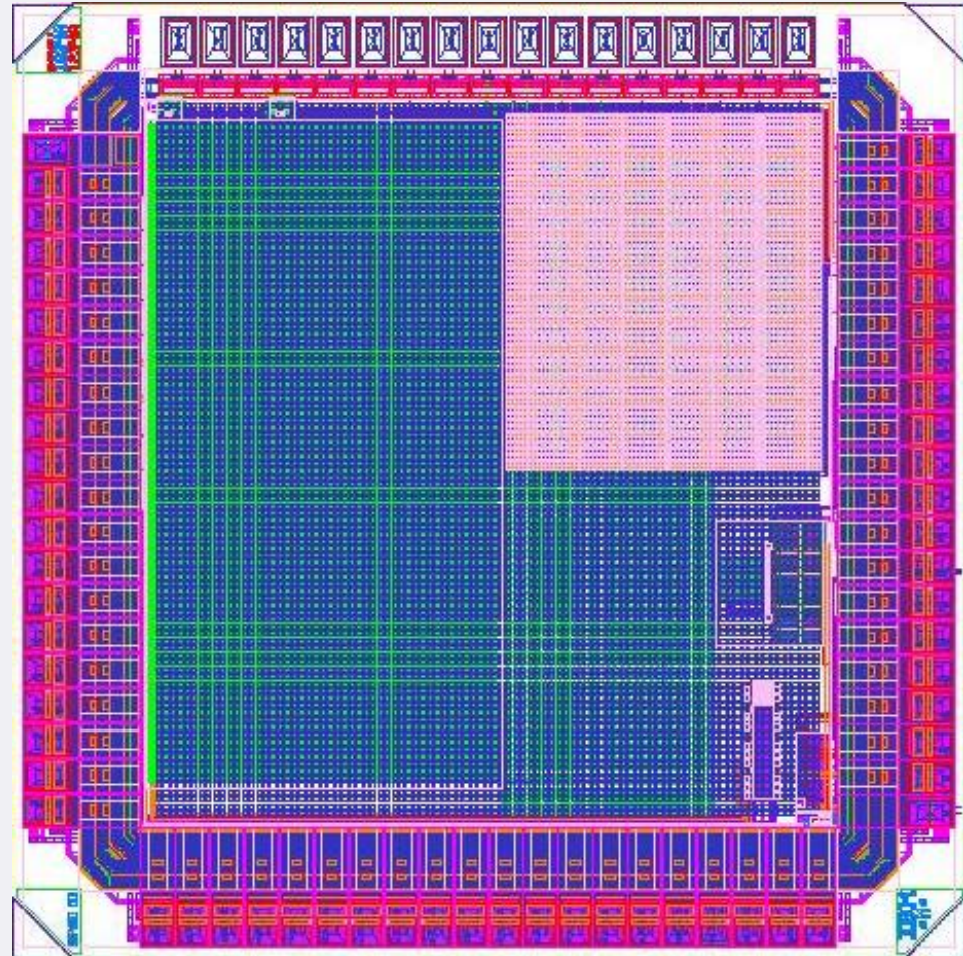
The “hpad 0.1” chip (DESY)

Intended for radiation and leakage current studies

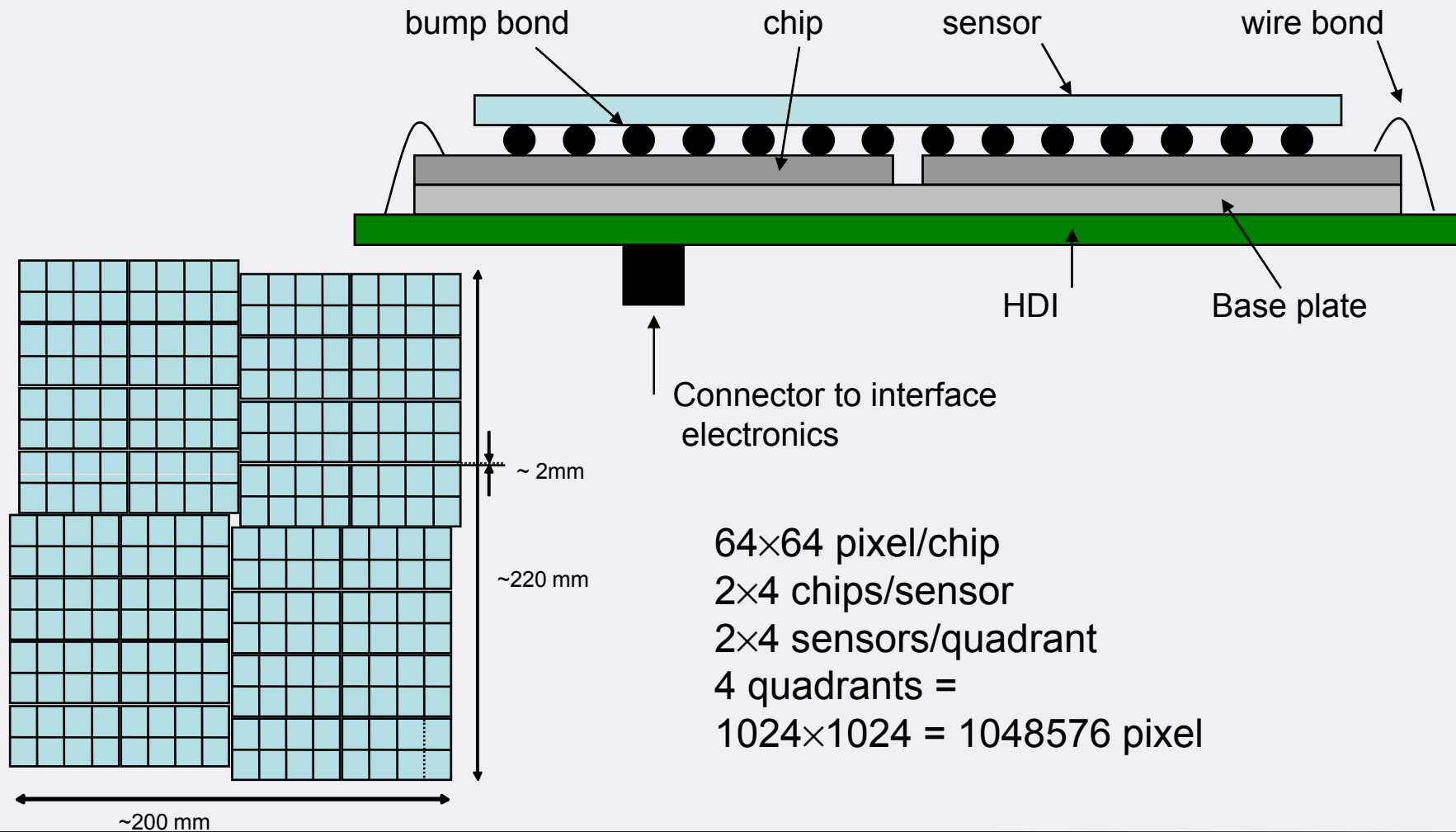
2mm x 2mm, submitted via MOSIS at
26.03.2008

Only test structures:

- Capacitors
- Switches (FETs)
- 16-cell analogue storage array
- OP-Amp & buffer amplifiers
- Minimum protection pad



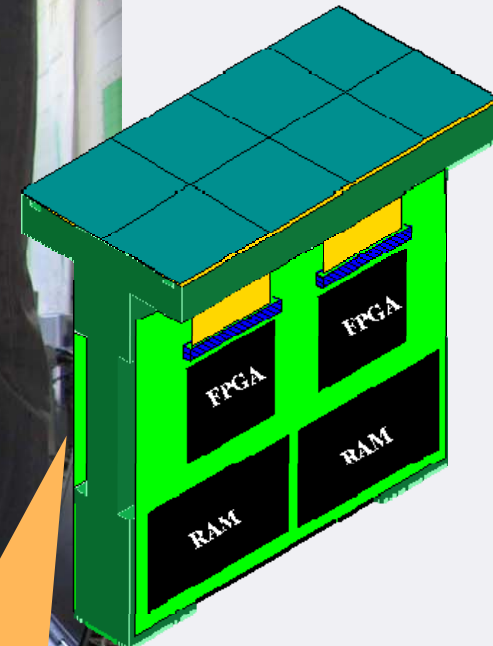
The Analogue-Pipeline HPAD (DESY)



HPAD: How things will look

The PILATUS 6M of the SLS@PSI

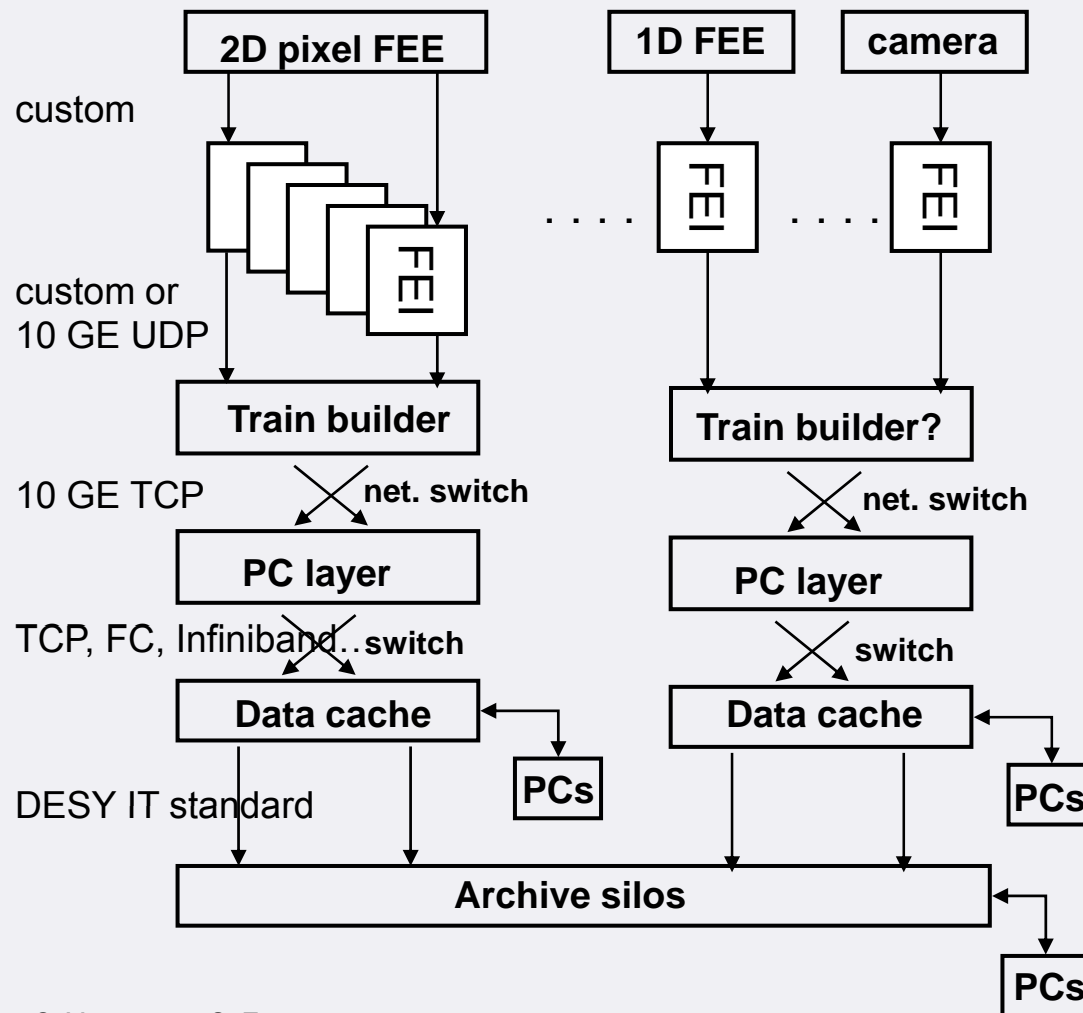
Pilatus XFS
Module



HPAD mechanics
will be based on
the Pilatus XFS

2x4 (8) Chips per
Module.
~78 x 39 mm² (XFS)
~50 x 27 mm² (HPAD)

XFEL DAQ architecture (DESY)



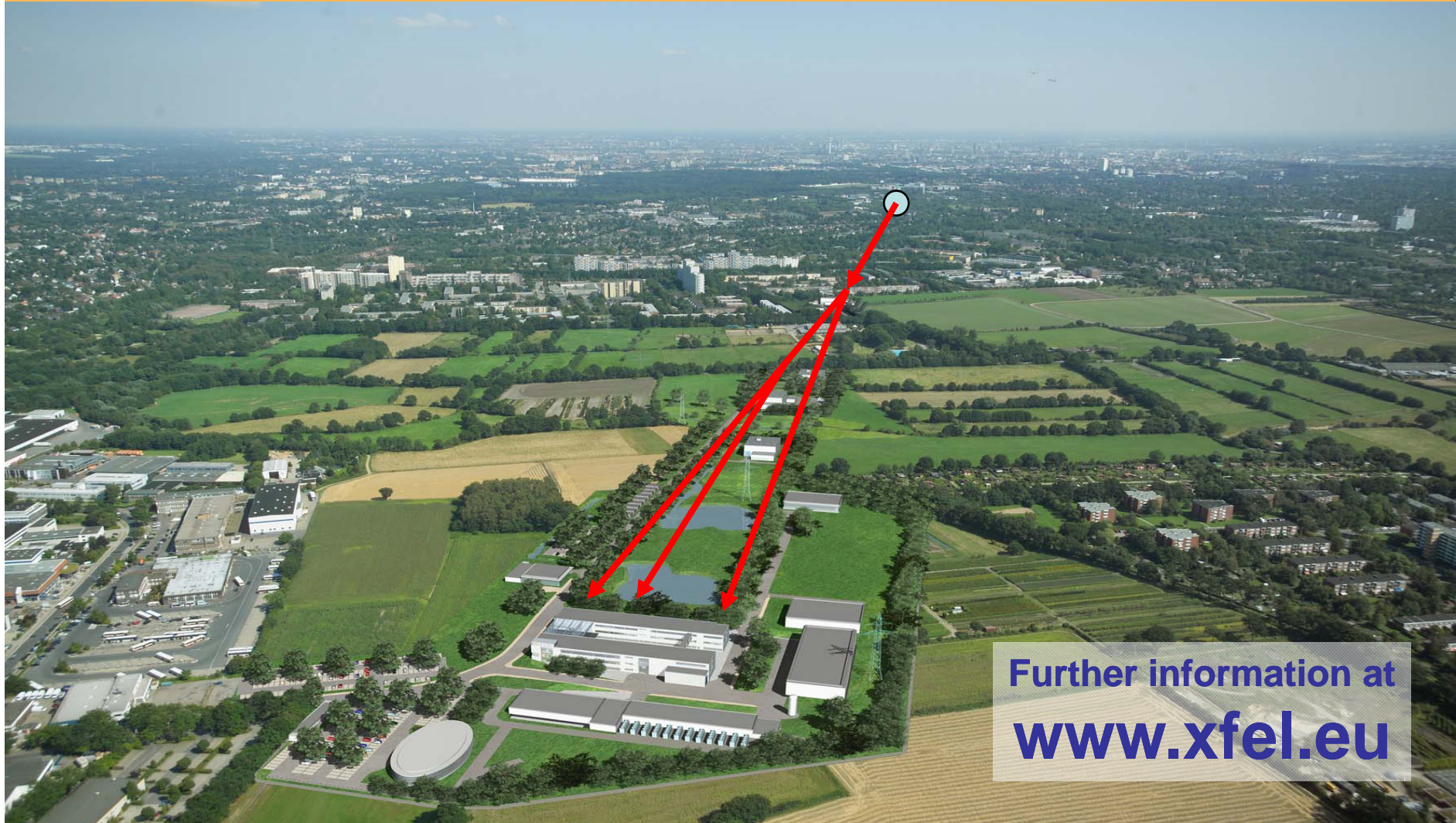
- Front End Electronics (FEE)
- Front End Interface (FEI)
 - interface to Train Builder.
 - maybe not needed by 2D
- Train builder layer
 - builds trains
 - simple data processing
 - maybe not needed by 1D and cameras.
- PC layer
 - interface to cache
 - additional train building (?)
 - more complex data process
- Data cache
 - hold, analyze, reduce and reject data
 - post processing commit to silo

C. Youngman, S. Esanov

Summary & Outlook

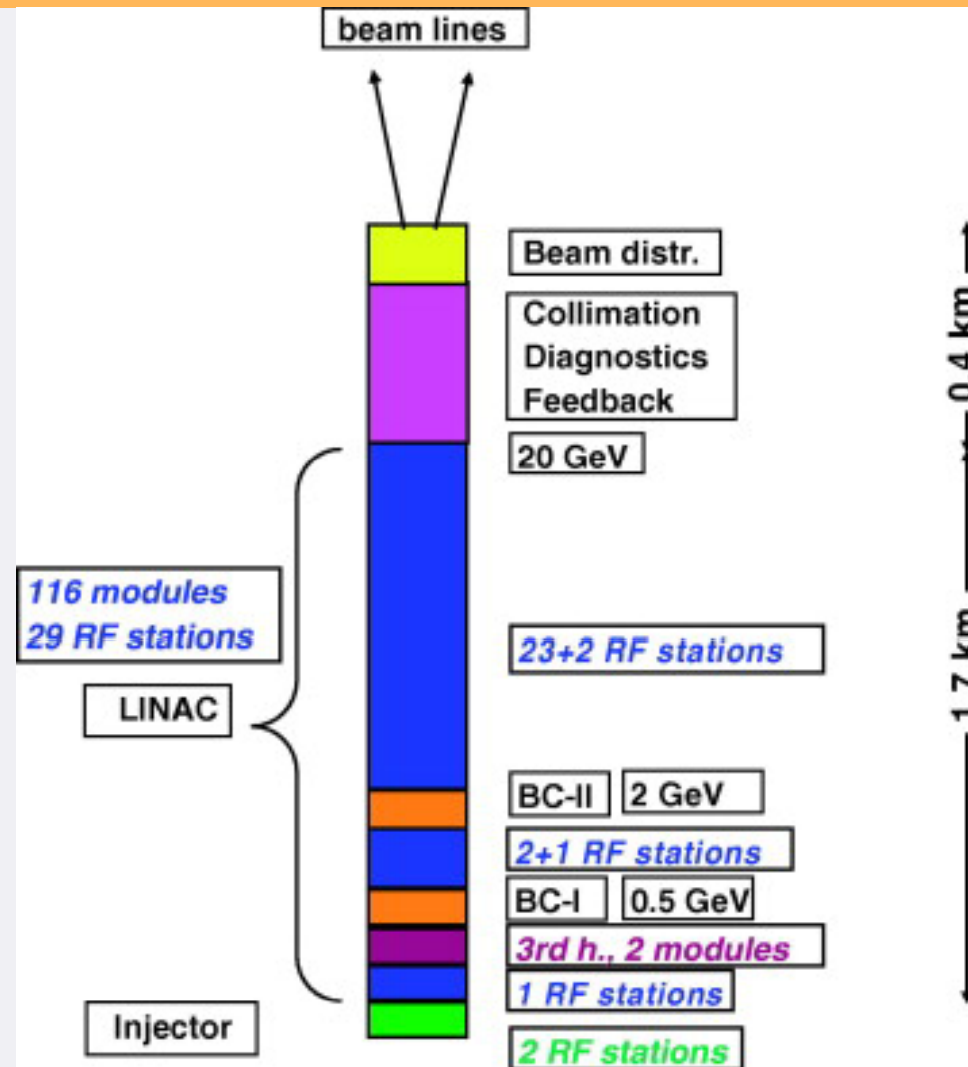
- Signing of the Contract for the XFEL GmbH (company) scheduled for end of 2008
 - Start of civil construction scheduled for Nov. 2008
- Accelerator
 - Modules similar to FLASH/TTF
 - Successfully tested prototypes exist
- Undulators
 - Modules based on those of FLASH
- 2D area detectors
 - 3 projects
 - Individual solutions to the dynamic range challenge
- Ongoing studies on possible obstacles
 - Charge Explosion
 - Radiation hardness (test chip)
- First pixels in silicon in 2009
- Full area detectors in 2012

The European XFEL in 2012

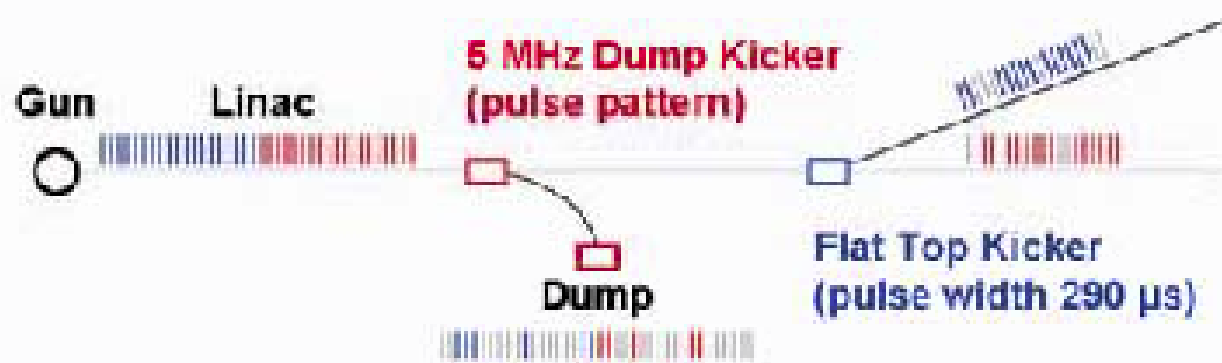


Further information at
www.xfel.eu

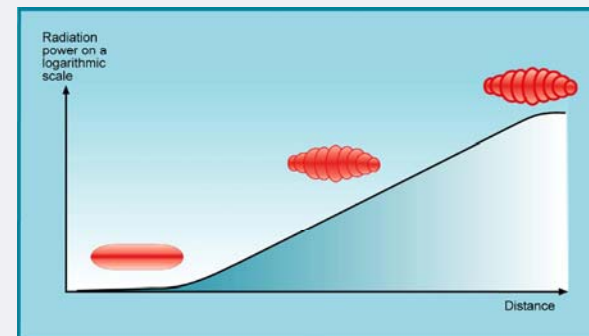
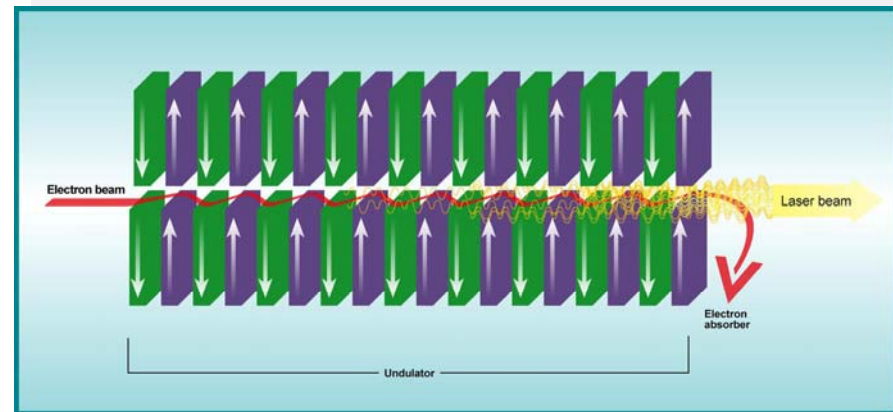
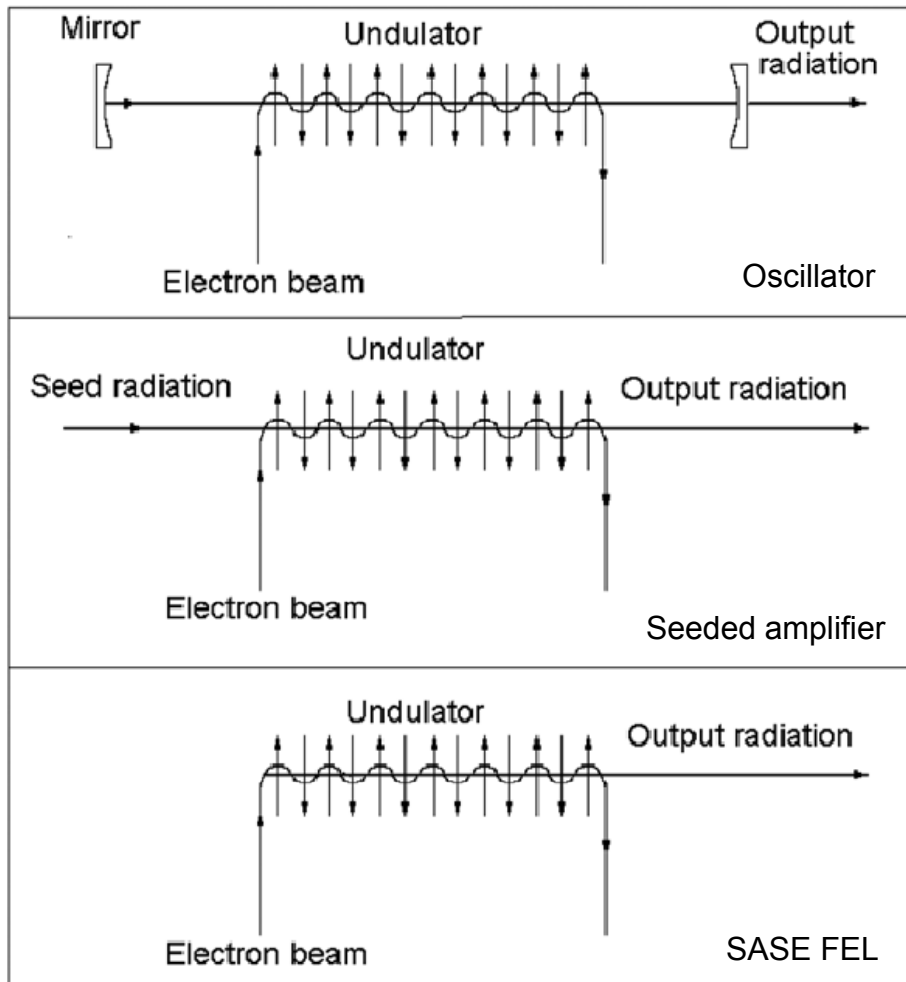
The Linac



Beam Distribution Kicker System

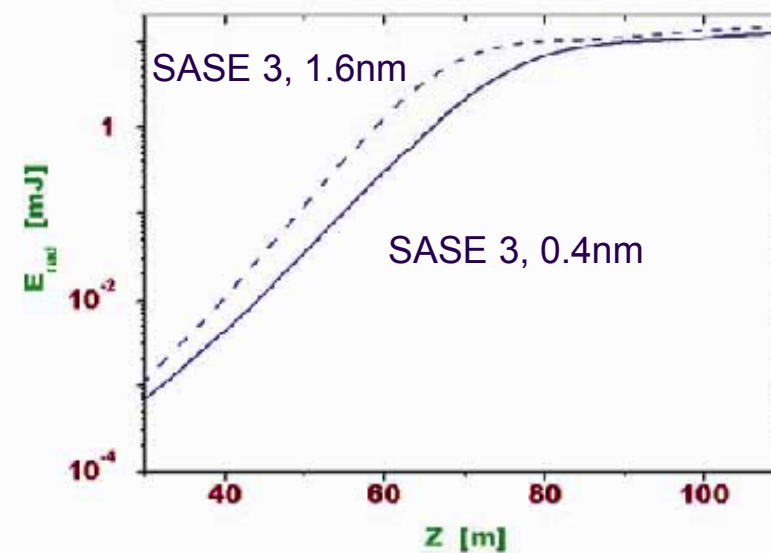
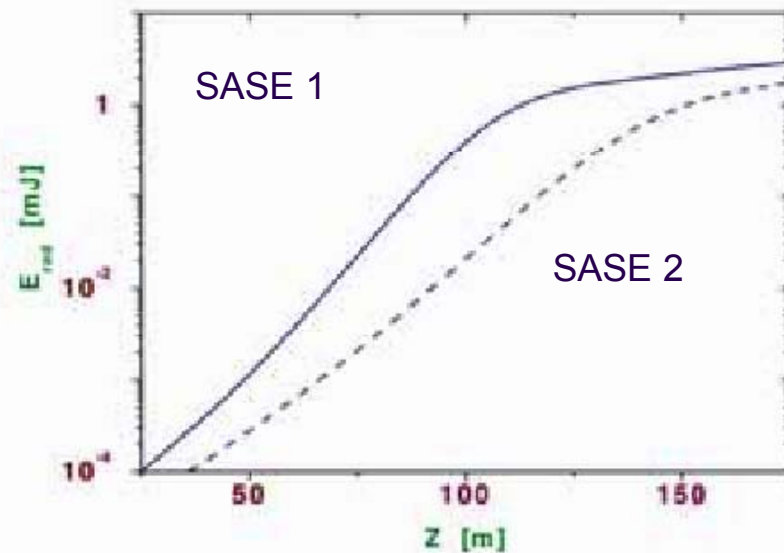


Synchrotron Radiation in FELs

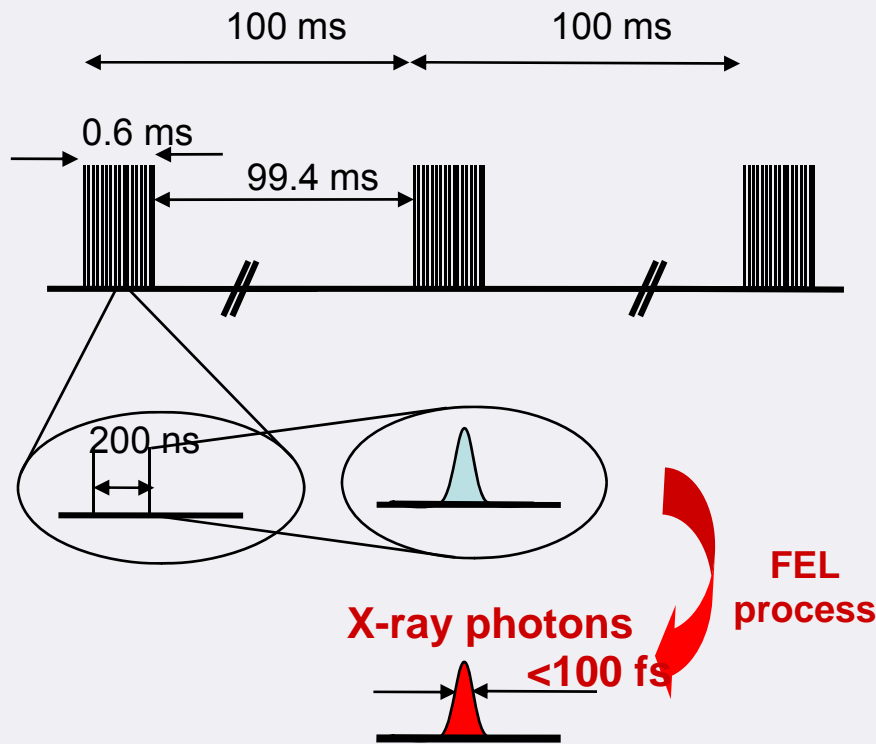


Undulators

	λ [nm]	λ_u [mm]	g [mm]	B_{\max} [T]	K	β [m]	L_{sat}^+ [m]	N_{tot}^{++} [5m]	L_{tot}^{+++} [m]
SASE 1*	0.1	35.6	10	1.0	3.3	32	133	33	201.3
SASE 2*	0.1	48	19	0.63	2.8	46	174	42	256.2
	0.4		10	1.37	6.1	15	72		
SASE 3**	0.4	80.0	23	0.44	3.3	15	81	21	128.1
	1.6		10	0.91	6.8	15	50		

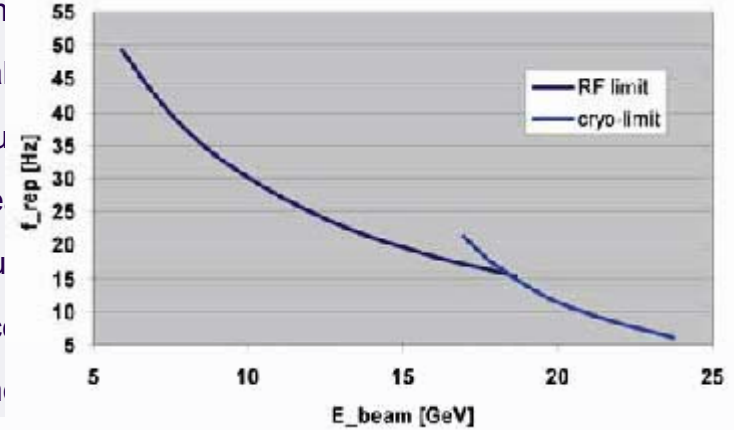


The Linac

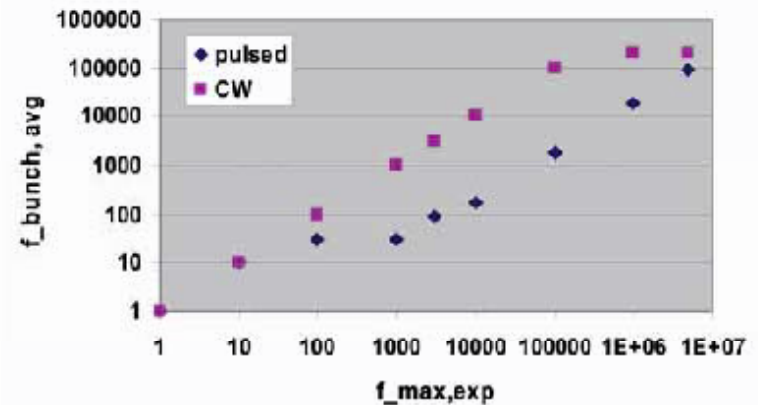


- W_m
- I_{pea}
- Q_{bu}
- P_{be}
- N_{bu}
- E_{ac}
- f_{bun}
- f_{cyc}
- 29
- 92
- 11
- P_R
- E_n
- Δt

max. linac repetition rate vs. beam energy
(constant beam pulse length 0.6ms)

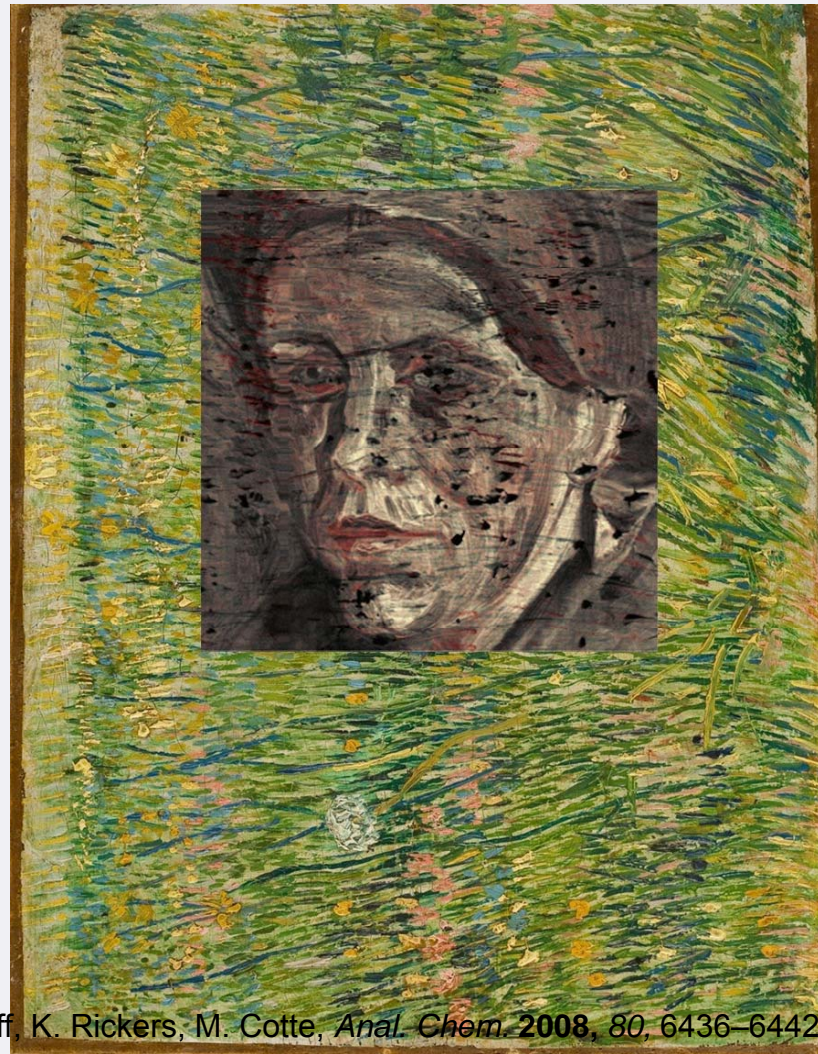


usable average bunch frequency vs. max bunch frequency for experiment



Experiments with Synchrotron Radiation

Visualization of a Lost Painting by Vincent van Gogh Using Synchrotron Radiation Based X-ray Fluorescence Elemental Mapping



J. Dik, K. Janssens, G. van der Snickt, L. van der Loeff, K. Rickers, M. Cotte, *Anal. Chem.* **2008**, *80*, 6436–6442

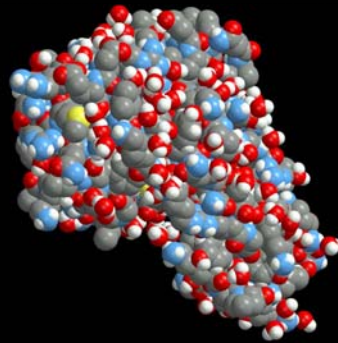
X-ray Photon Correlation Spectroscopy

Circular polarised
X-rays interact with
the magnetisation of
the sample

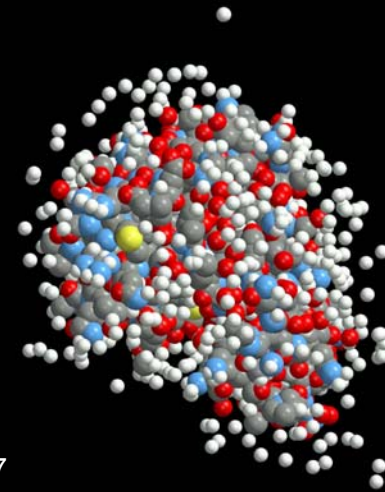
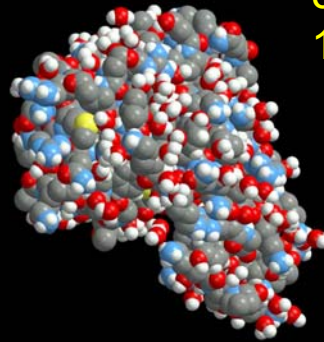
- Imaging of magnetic domains
- Studies of collective phenomena
- Investigation of phase transitions

Single Molecules & Coherent X-ray Imaging

Coulomb explosion of Lysozyme



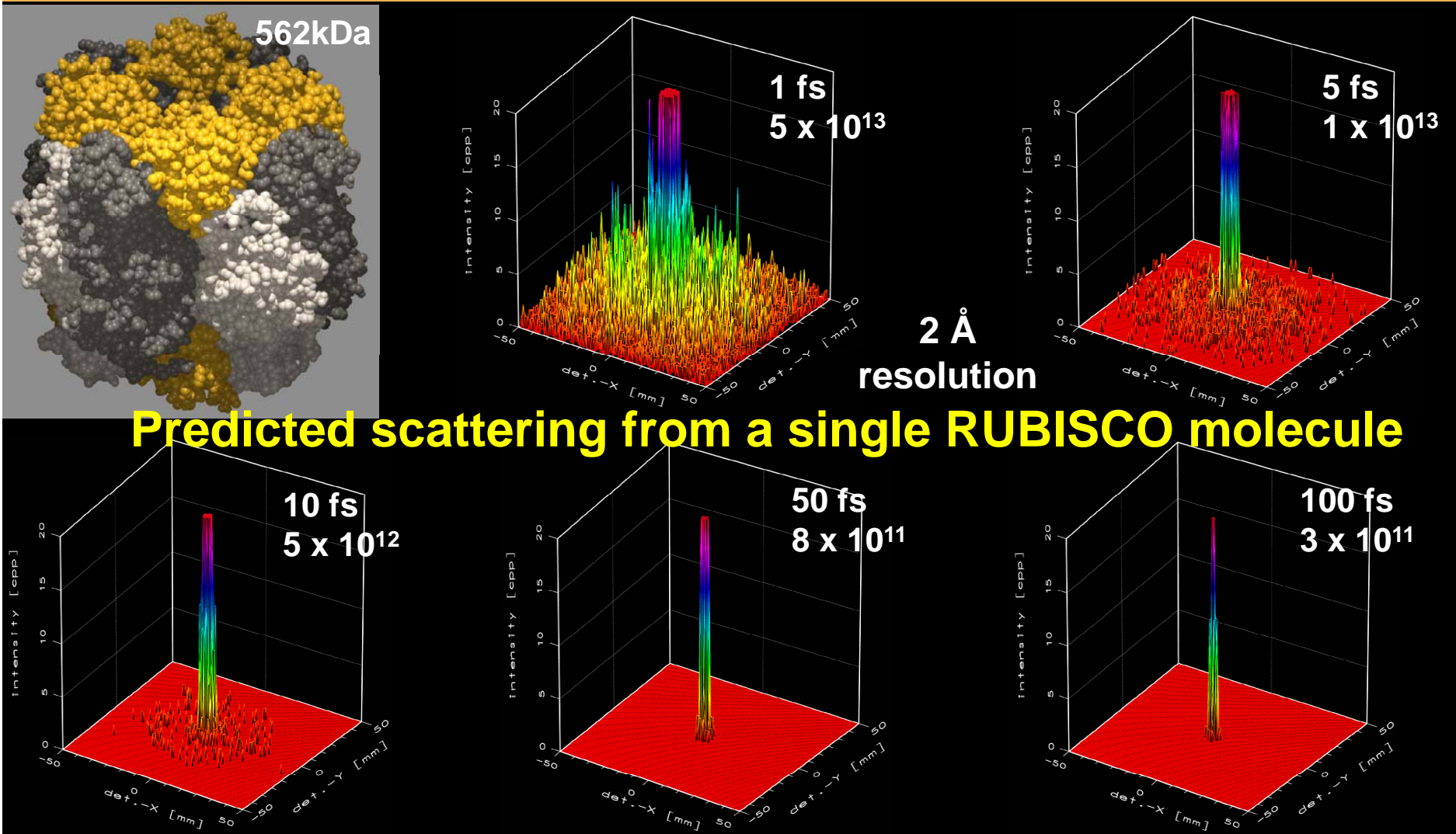
20 fs
 3×10^{12} photons/100 nm spot
12 keV



Radiation damage
interferes with atomic
positions and atomic
scattering factors

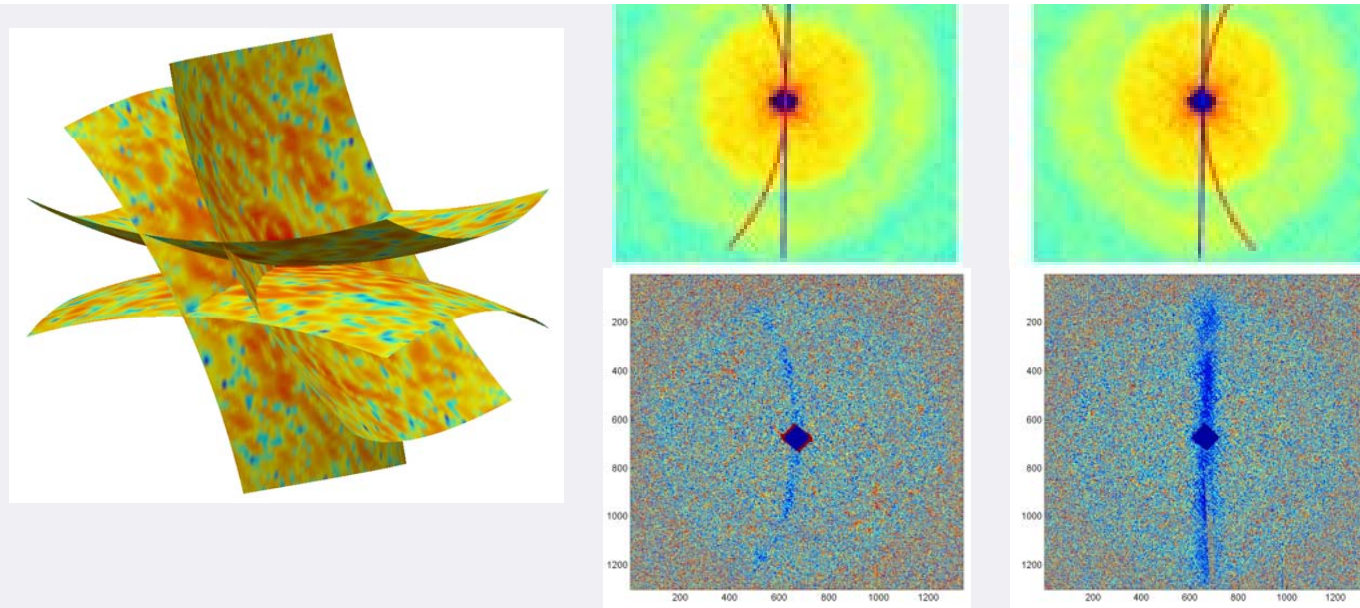
Neutze, R., Wouts, R., van der Spoel, D., Weckert, E. Hajdu, J. (2000) *Nature* 406, 752-757

Single Molecules & Coherent X-ray Imaging



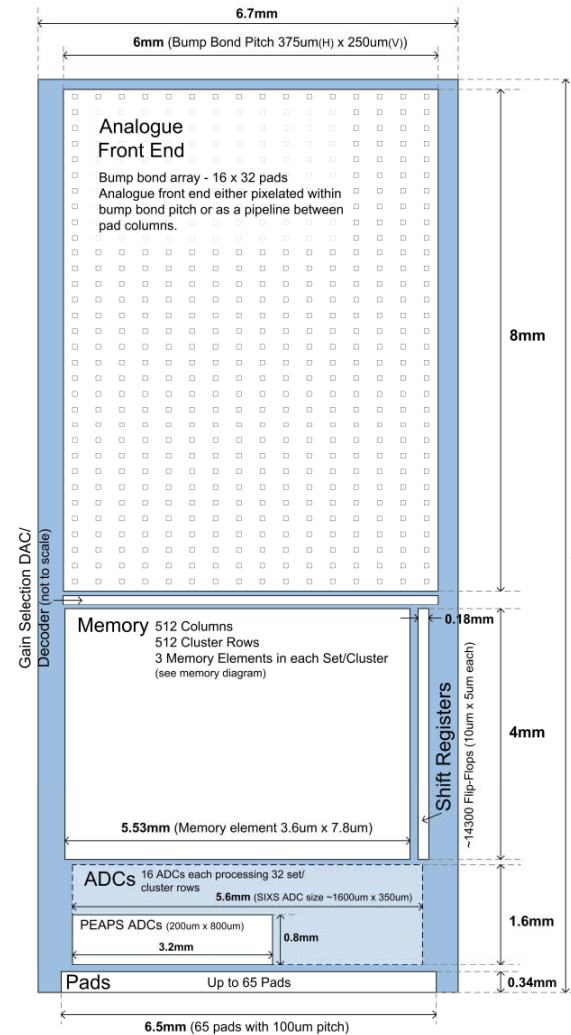
Single Particles & Coherent X-ray Imaging

Orientation, superposition & reconstruction



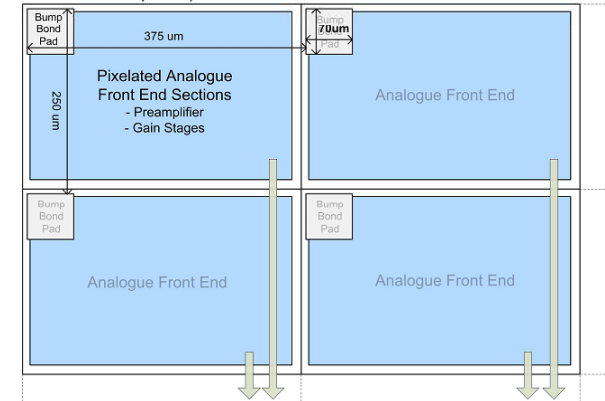
Intersection of two Ewald spheres with their centrosymmetric opposites. Centrosymmetry gives an extra intersect as there are *two* common arcs of intersection in *each* diffraction pattern (upper row). The images in the middle show the expected arcs of intersections in two diffraction patterns from the experimental pyramid x-ray diffraction data set from Figure 6.4.668. Images in the bottom row show these very lines of intersections when the experimentally obtained patterns are subtracted from each other pair wise [38].

LPD Memory Layout



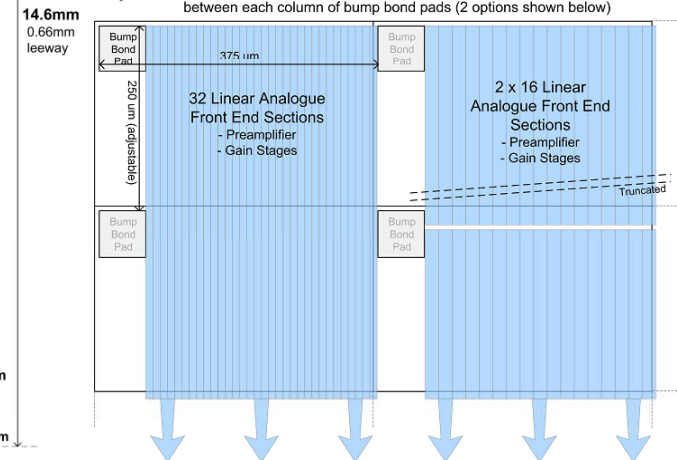
(STFC/RAL)

Pixelated - The front end has a pixelated arrangement with the same pitch as the bump bond pads



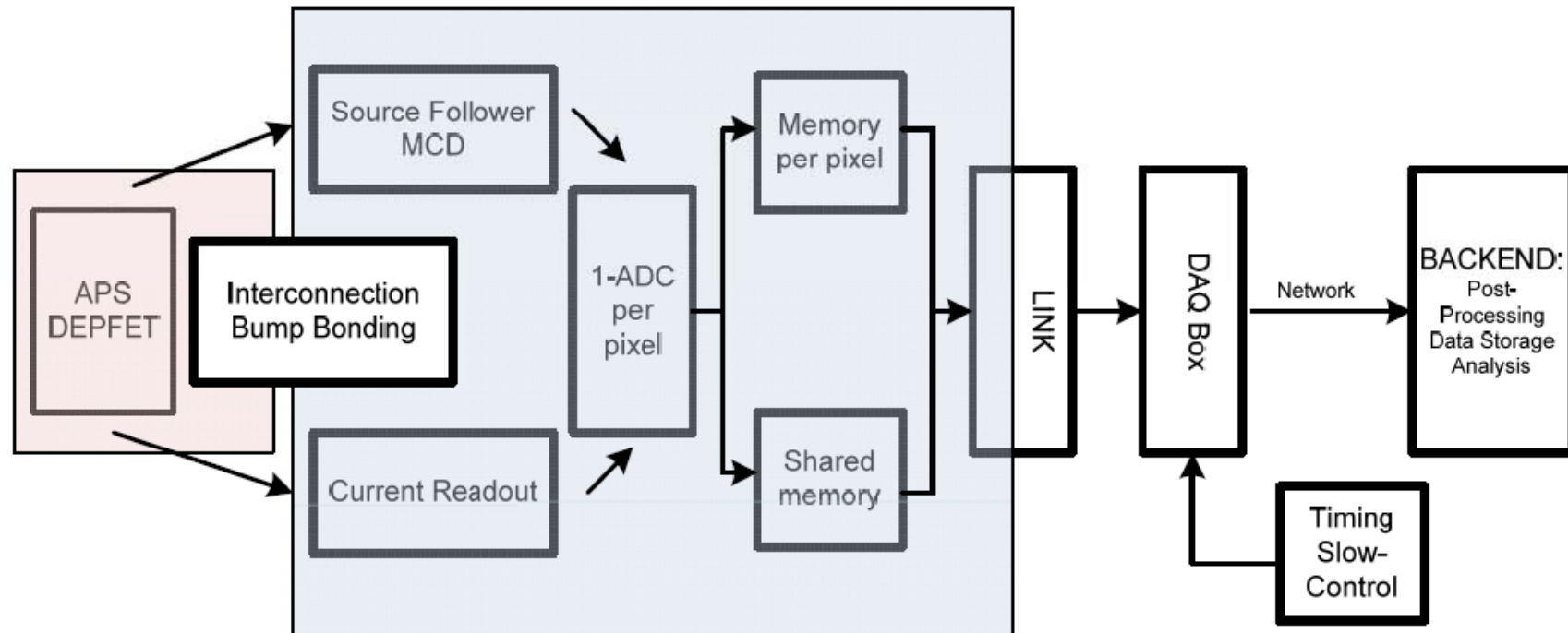
Amplifier outputs will be tracked out to the memory array.
Will use a clear routing track shielded to prevent coupling to other pix

Pipeline - The front end has a linear architecture with 2, 4, 8, 16 or 32 sections between each column of bump bond pads (2 options shown below)



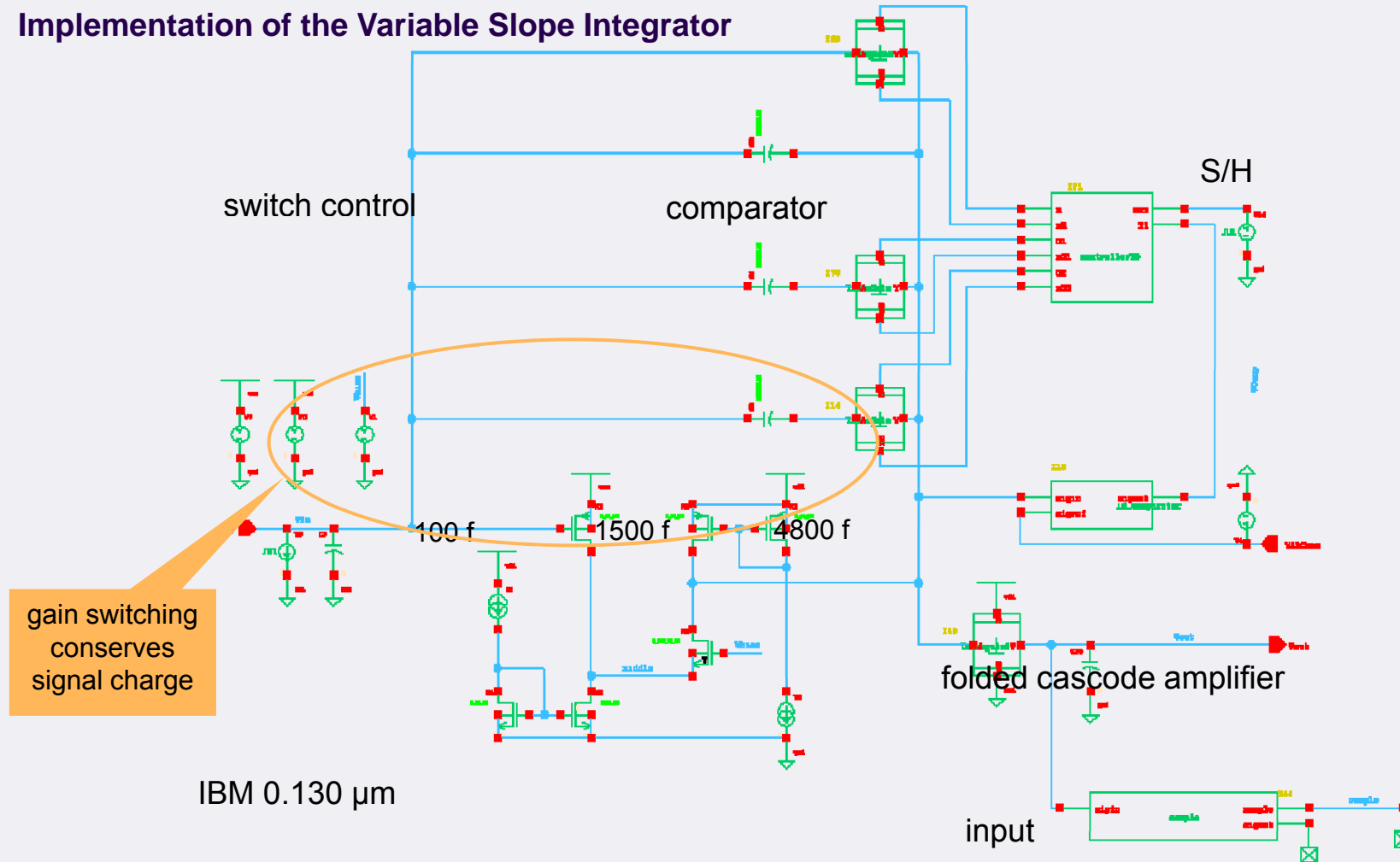
Extends through bump bond array and outputs to memory array

DEPFET Active Pixel Sensor Detector

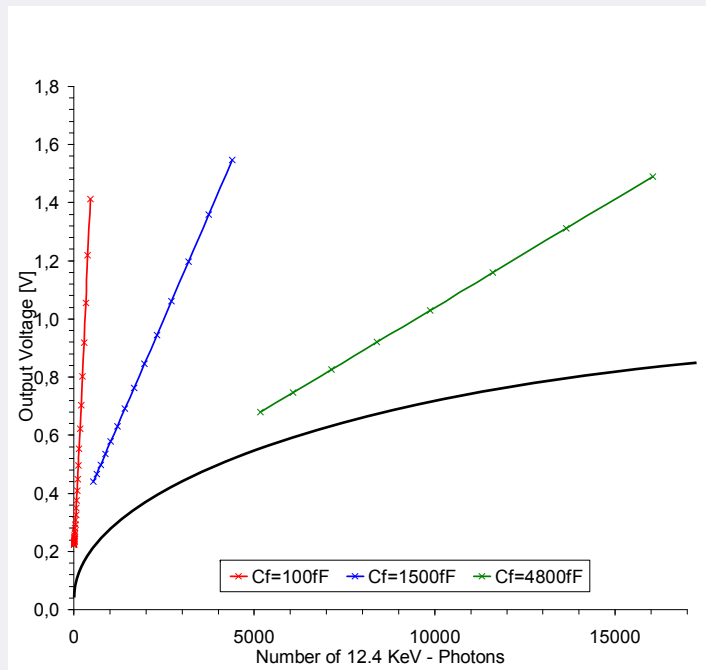


HPAD Simulation

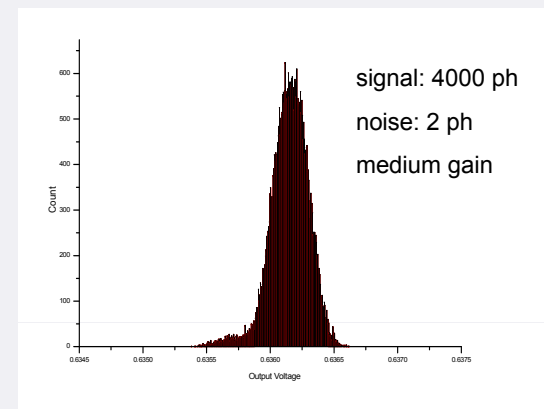
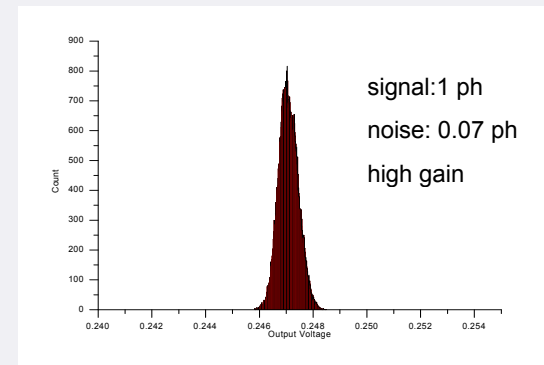
Implementation of the Variable Slope Integrator



HPAD Simulation Results



output voltage as a result of the
dynamic gain switching



output noise for two different input
signals (preliminary)